ISONIC 2009 UPA-Scope

Portable Ultrasonic Phased Array Flaw Detector and Recorder



Operating Manual Revision 1.24



ISONIC 2009 UPA-Scope from Sonotron NDT – Operating Manual – Revision 1.24 – Page 2 of 156

Information in this document is subject to change without notice. No part of this document may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, without the express written permission of:

Sonotron NDT, 4, Pekeris st., Rabin Science Park, Rehovot, Israel, 76702

Covered by the United States patents 5524627, 5952577, 6545681; other US & foreign patents pending



Sonotron NDT

4, Pekeris str., Rabin Science Park, Rehovot, 76702, Israel Phone:++972-(0)8-9477701 Fax:++972-(0)8-9477712 http://www.sonotronndt.com

EC Declaration of Conformity

Council Directive 89/336/EEC on Electromagnetic Compatibility, as amended by Council Directive 92/31/EEC & Council Directive 93/68/EEC Council Directive 73/23/EEC (Low Voltage Directive), as amended by Council Directive 93/68/EEC

We, **Sonotron NDT Ltd.**, 4 Pekeris Street, Rehovot, 76702 Israel, certify that the product described is in conformity with the Directives 73/23/EEC and 89/336/EEC as amended

ISONIC 2009 UPA-Scope

Portable Digital Phased Array Ultrasonic Flaw Detector and Recorder 64 channels phased array electronics and 1 / 8 / 16 independent channels for connection of conventional and TOFD probes

The product identified above complies with the requirements of above EU directives by meeting the following standards:

Safety

EN 61010-1:1993

EMC

EN 61326:1997 EN 61000-3-2:1995 /A1:1998 /A2:1998 /A14:2000 EN 61000-3-3:1995





Sonotron NDT

4, Pekeris str., Rabin Science Park, Rehovot, 76702, Israel Phone:++972-(0)8-9477701 Fax:++972-(0)8-9477712 http://www.sonotronndt.com

Declaration of Compliance

We, **Sonotron NDT Ltd.**, 4 Pekeris Street, Rehovot, 76702 Israel certify that the product described is in conformity with National and International Codes as amended

ISONIC 2009 UPA-Scope

Portable Digital Phased Array Ultrasonic Flaw Detector and Recorder 64 channels phased array electronics and 1 / 8 / 16 independent channels for connection of conventional and TOFD probes

The product identified above complies with the requirements of following National and International Codes:

- ASME Section I Rules for Construction of Power Boilers
- ASME Section VIII, Division 1 Rules for Construction of Pressure Vessels
- ASME Section VIII, Division 2 Rules for Construction of Pressure Vessels. Alternative Rules
- ASME Section VIII Article KE-3 Examination of Welds and Acceptance Criteria
- ASME Code Case 2235 Rev 9 Use of Ultrasonic Examination in Lieu of Radiography
- ASME Code Case 2541 Use of Manual Phased Array Ultrasonic Examination Section V
- ASME Code Case 2557 Use of Manual Phased Array S-Scan Ultrasonic Examination Per Article 4 Section V
- ASME Code Case 2558 Use of Manual Phased Array E-Scan Ultrasonic Examination Per Article 4 Section V
- Non-Destructive Examination of Welded Joints Ultrasonic Examination of Welded Joints. British and European Standard BS EN 1714:1998
- Non-Destructive Examination of Welds Ultrasonic Examination Characterization of Indications in Welds. – British and European Standard BS EN 1713:1998
- Calibration and Setting-Up of the Ultrasonic Time of Flight Diffraction (TOFD) Technique for the Detection, Location and Sizing of Flaws. – British Standard BS 7706:1993
- WI 00121377, Welding Use Of Time-Of-Flight Diffraction Technique (TOFD) For Testing Of Welds. – European Committee for Standardization – Document # CEN/TC 121/SC 5/WG 2 N 146, issued Feb, 12, 2003
- ASTM E 2373 04 Standard Practice for Use of the Ultrasonic Time of Flight iffraction (TOFD) Technique
- Non-Destructive Testing Ultrasonic Examination Part 5: Characterization and Sizing of Discontinuities. – British and European Standard BS EN 583-5:2001
- Non-Destructive Testing Ultrasonic Examination Part 2: Sensitivity and Range Setting. British and European Standard BS EN 583-2:2001
- Manufacture and Testing of Pressure Vessels. Non-Destructive Testing of Welded Joints. Minimum Requirement for Non-Destructive Testing Methods – Appendix 1 to AD-Merkblatt HP5/3 (Germany).– Edition July 1989



FCC Rules

This **ISONIC 2009 UPA-Scope** ultrasonic phased array flaw detector and data recorder (hereinafter called **ISONIC 2009 UPA-Scope**) has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna
- Increase the separation between the equipment and receiver
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected
- Consult the dealer or an experienced radio/TV technician for help

Safety Regulations



Please read this section carefully and observe the regulations in order to ensure your safety and operate the system as intended

Please observe the warnings and notes printed in this manual and on the unit

The **ISONIC 2009 UPA-Scope** has been built and tested according to the regulations specified in EN60950/VDE0805. It was in perfect working condition on leaving the manufacturer's premises

In order to retain this standard and to avoid any risk in operating the equipment, the user must make sure to comply with any hints and warnings included in this manual

Depending on the power supply the ISONIC 2009 UPA-Scope complies with protection class I /protective grounding/, protection class II, or protection class III

Exemption from statutory liability for accidents

The manufacturer shall be exempt from statutory liability for accidents in the case of non-observance of the safety regulations by any operating person

Limitation of Liability

The manufacturer shall assume no warranty during the warranty period if the equipment is operated without observing the safety regulations. In any such case, manufacturer shall be exempt from statutory liability for accidents resulting from any operation

Exemption from warranty

The manufacturer shall be exempt from any warranty obligations in case of the non-observance of the safety regulations The manufacturer will only warrant safety, reliability, and performance of the **ISONIC 2009 UPA-Scope** if the following safety regulations are closely observed:

- Setting up, expansions, re-adjustments, alterations, and repairs must only be carried out by persons who have been authorized by manufacturer
- The electric installations of the room where the equipment is to be set up must be in accordance with IEC requirements
- The equipment must be operated in accordance with the instructions
- Any expansions to the equipment must comply with the legal requirements, as well as with the specifications for the unit concerned
- Confirm the rated voltage of your ISONIC 2009 UPA-Scope matches the voltage of your power outlet
- The mains socket must be located close to the system and must be easily accessible
- Use only the power cord furnished with your ISONIC 2009 UPA-Scope and a properly grounded outlet /only protection class I/
- Do not connect the **ISONIC 2009 UPA-Scope** to power bar supplying already other devices. Do not use an extension power cord
- Any interruption to the PE conductor, either internally or externally, or removing the earthed conductor will make the system unsafe to use /only protection class I/
- Any required cable connectors must be screwed to or hooked into the casing
- The equipment must be disconnected from mains before opening
- To interrupt power supply, simply disconnect from the mains
- Any balancing, maintenance, or repair may only be carried out by manufacturer authorized specialists who are familiar with the inherent dangers
- Both the version and the rated current of any replacement fuse must comply with specifications laid down
- Using any repaired fuses, or short-circuiting the safety holder is illegal
- If the equipment has suffered visible damage or if it has stopped working, it must be assumed that it can no longer be operated without any danger. In these cases, the system must be switched off and be safeguarded against accidental use
- Only use the cables supplied by manufacturer or shielded data cable with shielded connectors at either end
- Do not drop small objects, such as paper clips, into the ISONIC 2009 UPA-Scope
- Do not put the ISONIC 2009 UPA-Scope in direct sunlight, near a heater, or near water. Leave space around the ISONIC 2009 UPA-Scope
- Disconnect the power cord whenever a thunderstorm is nearby. Leaving the power cord connected may damage the ISONIC 2009
 UPA-Scope or your property

- When positioning the equipment, external monitor, external keyboard, and external mouse take into account any local or national regulations relating to ergonomic requirements. For example, you should ensure that little or no ambient light is reflected off the external monitor screen as glare, and that the external keyboard is placed in a comfortable position for typing
- Do not allow any cables, particularly power cords, to trail across the floor, where they can be snagged by people walking past
- The voltage of the External DC Power Supply below 11 V is not allowed for the ISONIC 2009 UPA-Scope unit
- The voltage of the External DC Power Supply above 16 V is not allowed for the ISONIC 2009 UPA-Scope unit
- Charge of the battery for the ISONIC 2009 UPA-Scope unit is allowed only with use of the AC/DC converters / chargers supplied along with it or authorized by Sonotron NDT

Remember this before:

- balancing
- carrying out maintenance work
- repairing
- exchanging any parts

Please make sure batteries, rechargeable batteries, or a power supply with SELV output supplies power

Software (SW)

ISONIC 2009 UPA-Scope is a SW controlled inspection device. Based on present state of the art, SW can never be completely free of faults. **ISONIC 2009 UPA-Scope** should therefore be checked before and after use in order to ensure that the necessary functions operate perfectly in the envisaged combination. If you have any questions about solving problems related to use the **ISONIC 2009 UPA-Scope**, please contact your local Sonotron NDT representative

1. I	NTRODUCTION	10
2	ECHNICAL DATA	12
3. I	SONIC 2009 – SCOPE OF SUPPLY	16
4. (DPERATING ISONIC 2009	31
	I.1. PRECONDITIONS FOR ULTRASONIC TESTING WITH ISONIC 2009 UPA-SCOPE	
	I.2. ISONIC 2009 Controls and Terminals I.3. Turning On / Off	
5. I	PA MODALITY	39
	5.1. PA MODALITY START MENU	
	5.2. Standard and Optional Modes Of Operation 5.3. Wedged Linear Array Probes – Standard Modes of Operation	
į	5.3.1. Wedged Linear Array Probes Database	
	5.3.2. General Rule for Keying In / Modifying Parameter	47
	5.3.3. ISONIC PA Pulser Receiver – Wedged Linear Array Probes	48
	5.3.3.1. Operating Surface 5.3.3.2. Sub Menu BASICS	
	5.3.3.3. Sub Menu PULSER	
	5.3.3.4. Sub Menus EMIT and RECEIVE	
	5.3.3.4.1. Definitions	51
	5.3.3.4.2. Pulser Mode = SINGLE – Full Matching of Emitting and Receiving Aperture 5.3.3.4.3. Pulser Mode = DUAL – Partial Matching of Emitting and Receiving Aperture	51
	5.3.3.4.4. Material Thickness	53
	5.3.3.5. Sub Menu RECEIVER	
	5.3.3.6. Sub Menus GATE A and GATE B 5.3.3.7. Sub Menu ALARM	
	5.3.3.7. Sub Menu ALARM	
	5.3.3.9. Create / Modify DAC	59
	5.3.3.9.1 Theoretical DAC: dB/mm (dB/in)	
	5.3.3.9.2 Experimental DAC: Recording Signals From Variously Located Reflectors	61
	5.3.3.10. Sub Menu MEASORE	64
	5.3.3.11.1. Measured Values	64
	5.3.3.11.2. Measuring Modes	
	5.3.3.11.3. Thickness Correction 5.3.3.12. Freeze A-Scan	
	5.3.3.12. Freeze A-Scan and Calibration Data Into a File	
	5.3.3.14. Load A-Scan and Calibration Data From a File	69
	5.3.3.15. Print A-Scan Settings List	
	5.3.3.16. Preview Current PA Probe in Use 5.3.3.17. Direction of Graphical Presentation	
	5.3.3.18. Activate Main Recording Menu	
	5.3.3.19. Return to Linear Array Probes Database	69
	5.3.4. Main Recording Menu	
	5.3.4.1. ABI Scan (B-Scan, E-Scan) 5.3.4.1.1. Settings of PA Pulser Receiver	
	5.3.4.1.2. Gain Per Shot Correction	
	5.3.4.1.3. B-Scan – ABI Scan Screen	74
	5.3.4.1.4. Color Palette – ABI Scan Screen	75
	5.3.4.1.5. 3D Data Recording Through Linear Scanning (C-Scan, Top and Side Views)	
	5.3.4.2. Sector Scan (S-Scan) 5.3.4.2.1. Settings of PA Pulser Receiver	
	5.3.4.2.2. Angle Gain Compensation	
	5.3.4.2.3. S-Scan – Sector Scan Screen	80
	5.3.4.2.4. Color Palette – Sector Scan Screen	
	5.3.4.2.5. 3D Data Recording Through Linear Scanning (C-Scan, Top and Side Views) 5.3.4.3. Tandem B-Scan	
	5.3.4.3.1 Preliminary Settings of PA Pulser Receiver	
	5.3.4.3.2. Region of Interest	82
	5.3.4.3.3. Calibration Block For Tandem B-Scan Technology	83
	5.3.4.3.4. Automatic Ray Tracing	
	5.3.4.3.5. Setting Gain For Tandem B-Scan Technology 5.3.4.3.6. Gain Per Shot Correction	

5.3.4.3.7. Tandem B-Scan	87
5.3.4.3.8. Color Palette – Tandem Scan Screen	
5.3.4.3.9. 3D Data Recording Through Linear Scanning (C-Scan, Top and Side Views) 5.4. LINEAR ARRAY PROBES WITH STRAIGHT DELAY LINE – STANDARD MODES OF OPERATION	87
5.5. OPTIONAL SW PACKAGES AND UTILITIES	
5.5.1. Options Menu	
5.5.2. Linear Array PA Probes	
5.5.2.1. K _{is} Optional SW Utility – Delta Technique	
5.5.2.2. CDM Optional Utility – Sizing Of Near Surface Cracks (Crack Depth Measurement)	
5.5.2.3. Lateral Scanning Optional Inspection SW Package	
5.5.2.3.1. Probe selection	
5.5.2.3.2. ISONIC PA Pulser Receiver 5.5.2.3.3. Modes of Lateral Scanning and Imaging	
5.5.2.3.4. Linear Scan	99 QQ
5.5.2.3.5. Azimuth Scan	
5.5.2.4. EXPERT – Optional Inspection SW Package For Welds	
5.5.2.4.1. B-Scan	101
5.5.2.4.2. Sector-Scan	
5.5.2.4.3. Weld Cross Section Geometry Settings	105
5.5.2.5. EXPERT CU – Optional Inspection SW Package For Tubular Objects, Rods, and Welds 5.5.2.5.1. Circumferential Insonification	
5.5.2.5.1. Circumerential insonnication	113
5.5.2.5.3. Inspection of Rods and Tube Walls	
5.5.2.5.4. Inspection of Welds	
5.5.2.5.5. Weld Cross Section Geometry Settings	
5.5.2.6. VLFS – Optional Inspection SW Package	
5.5.2.6.1. B-Scan	
5.5.2.6.2. Sector-Scan	
5.5.2.7. VLFS CU – Optional Inspection SW Package 5.5.2.8. Multi-Group – Optional Inspection SW Utility	
5.5.2.8. Multi-Group – Optional Inspection SW Otility	
5.5.3.1. Matrix Delay Line 3D Scan L – Optional Inspection SW Package for Compression Wave Inspectio	
5.5.3.1.1. Database of Matrix Arrays With / Without Delay Line	
5.5.3.1.2. ISONIC PA Pulser Receiver for Matrix Arrays With / Without Delay Line	130
5.5.3.1.3. Region of Interest (ROI)	
5.5.3.1.4. 3D Scan L Mode of Inspection and Imaging	131
5.5.3.2. Matrix Wedge 3D Scan S – Optional Inspection SW Package for Shear Wave Inspection	
5.5.3.2.1. Database of Wedged Matrix Arrays 5.5.3.2.2. ISONIC PA Pulser Receiver for Wedged Matrix Arrays	
5.5.3.2.3. 3 D Scan S: Scanning Modes	
5.5.3.2.4. 3D Scan S: VPFS – Vertical Plane Focusing Scanning	
5.5.3.2.5. 3D Scan S: EXPERT – Inspection of Welds	
5.6. VIEWING AND PROCESSING OF RECORDED FILES – PA MODALITY	
5.6.1. Posptorocessing on board ISONIC 2009 UPA Scope	
5.6.2. Posptorocessing in the PC	141
5.6.2.1. ISONIC 2009 PP Postprocessing Package 5.5.2.2. PUZZLE Postrocessing SW Package	
6. CONVENTIONAL PE AND TOFD MODALITIES	142
7. INCREMENTAL ENCODERS	144
	4.40
8. MISCELLANEOUS	
8.1. INTERNATIONAL SETTINGS	
8.2. PRINTER SELECTION	
8.3. EXIT TO WINDOWS	
8.4. CONNECTION TO NETWORK	-
8.5.1. Mouse	-
8.5.2. Keyboard	
8.5.3. Memory Stick (Disk on Key)	
8.5.4. Printer	150
8.6. EXTERNAL VGA SCREEN / VGA PROJECTOR	
8.7. SW UPGRADE	
8.8. CHARGING BATTERY	
0.9. OILIUUN RUBBER JAURE I	151

1. Introduction

ISONIC 2009 UPA Scope uniquely combines phased array, single- and multi-channel conventional UT, and TOFD modalities providing 100% raw data recording and imaging. Along with portability, lightweight, and battery operation this makes it suitable for all kinds of every-day ultrasonic inspections

Phased array modality is performed by powerful 64:64 phased array electronics with independently adjustable emitting and receiving aperture, each may consist of 1 through 64 elements. Each channel is equipped with it's own A/D converter. Parallel firing, A/D conversion, and "on-the-fly" digital phasing are provided for every possible composition and size of the emitting and receiving aperture. Thus implementation of each focal law is completed within single pulsing / receiving cycle providing maximal possible inspection speed

Depending on configuration **ISONIC 2009 UPA Scope** carries 1, 8, or 16 additional independent pulsingreceiving channels with single and dual modes of operation to fulfill conventional UT, and TOFD modalities

High ultrasonic performance is achieved through firing phased array, TOFD, and conventional probes with bipolar square wave initial pulse. Duration and amplitude of the initial pulse are wide-range-tunable. Initial pulse may reach 300 V pp for phased array and 400 V pp for conventional channels. Special circuit provides high stability of the amplitude and shape of the initial pulse, boosting of all it's leading and falling edges, and electronic damping. This significantly improves signal to noise ratio and resolution. The analogue gain for each modality is controllable over 0...100 dB range

Large 800X600 pixels 8.5" bright screen provides fine resolution for all types of data presentation

ISONIC 2009 UPA Scope is fully compliant with the following codes

- ASME Code Case 2541 Use of Manual Phased Array Ultrasonic Examination Section V
- ASME Code Case 2557 Use of Manual Phased Array S-Scan Ultrasonic Examination Section V per Article 4 Section V
- ASME Code Case 2558 Use of Manual Phased Array E-Scan Ultrasonic Examination Section V per Article 4 Section V
- ASTM 1961–06 Standard Practice for Mechanized Ultrasonic Testing of Girth Welds Using Zonal Discrimination with Focused Search Units
- ASME Section I Rules for Construction of Power Boilers
- ASME Section VIII, Division 1 Rules for Construction of Pressure Vessels
- ASME Section VIII, Division 2 Rules for Construction of Pressure Vessels. Alternative Rules
- ASME Section VIII Article KE-3 Examination of Welds and Acceptance Criteria
- ASME Code Case 2235 Rev 9 Use of Ultrasonic Examination in Lieu of Radiography
- Non-Destructive Examination of Welded Joints Ultrasonic Examination of Welded Joints. British and European Standard BS EN 1714:1998
- Non-Destructive Examination of Welds Ultrasonic Examination Characterization of Indications in Welds. – British and European Standard BS EN 1713:1998
- Calibration and Setting-Up of the Ultrasonic Time of Flight Diffraction (TOFD) Technique for the Detection, Location and Sizing of Flaws. – British Standard BS 7706:1993
- WI 00121377, Welding Use Of Time-Of-Flight Diffraction Technique (TOFD) For Testing Of Welds. – European Committee for Standardization – Document # CEN/TC 121/SC 5/WG 2 N 146, issued Feb, 12, 2003
- ASTM E 2373 04 Standard Practice for Use of the Ultrasonic Time of Flight Diffraction (TOFD) Technique
- Non-Destructive Testing Ultrasonic Examination Part 5: Characterization and Sizing of Discontinuities. – British and European Standard BS EN 583-5:2001
- Non-Destructive Testing Ultrasonic Examination Part 2: Sensitivity and Range Setting. British and European Standard BS EN 583-2:2001
- Manufacture and Testing of Pressure Vessels. Non-Destructive Testing of Welded Joints. Minimum Requirement for Non-Destructive Testing Methods – Appendix 1 to AD-Merkblatt HP5/3 (Germany).– Edition July 1989

2. Technical Data

Phased Array Pulse Type: Initial Transition: Pulse Amplitude: Half Wave Pulse Duration: Probe Types: Emitting aperture:	Bipolar Square Wave with electronically controlled damping ≤7.5 ns (10-90% for rising edges / 90-10% for falling edges) Smoothly tunable (12 levels) 50V 300 V pp into 50 Ω 50600 ns controllable in 10 ns step Linear / Ring / Matrix Array 164
Phasing (emitting aperture): Receiving Aperture:	0…100 μs with 5 ns resolution 1…64
Gain: Advanced Low Noise Design:	0100 dB controllable in 0.5 dB resolution 85 μV peak to peak input referred to 80 dB gain / 25 MHz bandwidth
Frequency Band: A/D Conversion:	0.2 … 25 MHz Wide Band 100 MHz 16 bit
Superimposing of receiving aperture signals:	On-the-fly, no multiplexing involved
Phasing (receiving aperture): A-Scan Display Modes: DAC / TCG – for rectified and RF display:	On-the-fly 0…100 μs with 5 ns resolution RF, Rectified (Full Wave / Negative or Positive Half Wave) Theoretical – dB/mm (dB/") Experimental – through recording echoes from several reflectors
Gates per focal law: Gate Start and Width:	46 dB Dynamic Range, Slope \leq 20 dB/µs, Capacity \leq 40 points 2 Independent Gates / unlimitedly expandable Controllable over whole variety of A-Scan Display Delay and A-
Gate Threshold: Number of focal laws:	Scan Range in 0.1 mm /// 0.001" resolution 5…95 % of A-Scan height controllable in 1 % resolution 8192
Scanning and Imaging:	B-Scan (E-Scan) – regular and True-To-Geometry Sector Scan (S-Scan) – regular and True-To-Geometry One-probe multi-group image composed from several B- and S- Scans
	Tandem-B-Scan – True-To-Geometry (for the detection of planar vertically oriented defects) Top (C-Scan), Side, End View imaging formed through encoded / time-based line scanning, 3D-Viewer
Method of data storage:	Real time 3D-Scan composed with use of Matrix Array Probes 100% raw data capturing

Conventional UT and TOFD

Number of Channels	1 or 8 or 16
Pulsing/Receiving Methods (for 8	Parallel - all channels do fire, receive, digitize, and record signals
or 16 conventional channels):	simultaneously
· · · · · · · · · · · · · · · · · · ·	Sequential – cycles of firing, receiving, digitizing, and recording
	signals by each channel are separated in time in a sequence loop
Pulse Type:	Bipolar Square Wave with electronically controlled damping
Initial Transition:	≤7.5 ns (10-90% for rising edges / 90-10% for falling edges)
Pulse Amplitude:	Smoothly tunable (12 levels) 50V 400 V pp into 50 Ω
Half Wave Pulse Duration:	50600 ns independently controllable in 10 ns step
Modes:	Single / Dual
Gain:	0100 dB controllable in 0.5 dB resolution
Advanced Low Noise Design:	$85 \mu\text{V}$ peak to peak input referred to 80 dB gain / 25 MHz
	bandwidth
Frequency Band:	0.2 25 MHz Wide Band
A/D Conversion:	100 MHz 16 bit
Digital Filter:	32-Taps FIR band pass with controllable lower and upper
3	frequency limits
A-Scan Display Modes:	RF, Rectified (Full Wave / Negative or Positive Half Wave), Signal's
	Spectrum (FFT Graph)
DAC / TCG – for rectified and RF	Theoretical – dB/mm (dB/")
display:	Experimental – through recording echoes from several reflectors
	46 dB Dynamic Range, Slope \leq 20 dB/ μ s, Capacity \leq 40 points
DGS:	Standard Library for 18 probes / unlimitedly expandable
Gates:	2 Independent Gates / unlimitedly expandable
Gate Start and Width:	Controllable over whole variety of A-Scan Display Delay and A-
	Scan Range
	in 0.1 mm /// 0.001" resolution
Gate Threshold:	595 % of A-Scan height controllable in 1 % resolution
Measuring Functions – Digital	27 automatic functions / expandable; Dual Ultrasound Velocity
Display Readout:	Measurement Mode for Multi-Layer Structures; Curved Surface /
	Thickness / Skip correction for angle beam probes; Ultrasound
Freeze (A. Seene and Speetrum	velocity and Probe Delay Auto-Calibration for all types of probes
Freeze (A-Scans and Spectrum	Freeze All / Freeze Peak – signal evaluation, manipulating Gates
Graphs): Scanning and Imaging:	and Gain is possible for frozen signals as for live Single Channel: Thickness Profile B-Scan, Cross-sectional B-
Scanning and imaging.	Scan, Plane View CB-Scan, TOFD
	Multi-Channel: Strip Charts of 4 types (Amplitude/TOFD P/E, Map,
	TOFD, Coupling)
Standard Length of one Line	5020000 mm (2"800"), automatic scrolling
Scanning record:	
Method of data storage:	100% raw data capturing
-	

General PRF: On-Board Computer CPU: RAM: Internal Flash Memory - Quasi HDD:	105000 Hz controllable in 1 Hz resolution AMD LX 800 - 500MHz ≥ 512 Megabytes ≥ 4 Gigabytes
Screen:	Sun readable 8.5" touch screen 800 × 600
Controls:	Sealed keyboard and mouse
Interface:	2 × USB, Ethernet
Operating System:	Windows™XP Embedded
Encoder interface:	Incremental TTL encoder
Housing:	IP 53 rugged aluminum case with carrying handle
Dimensions:	314×224×124 mm (12.36"×8.82"×4.88") – without battery
Weight:	314×224×152 mm (12.36"×8.82"×5.98") – with battery 4.550 kg (10.01 lbs) – without battery 5.480 kg (12.06 lbs) – with battery

3. ISONIC 2009 – Scope of Supply

ISONIC 2009 UPA-Scope from Sonotron NDT – Operating Manual – Revision 1.24 – Page 16 of 156

#	Item	Order Code (Part #)	Note
1	 ISONIC 2009 UPA-Scope – Portable Digital Phased Array Ultrasonic Flaw Detector and Recorder: 64 channels PA electronics and 1 independent channel for connection of conventional and TOFD probes ISONIC 2009 UPA-Scope Electronic unit – including: Internal PC (AMD LX 800 500 MHz, RAM-512M, Quazi-HDD Flash Memory Card 4G, Windows XP Embedded, Large 8.5" active TFT sVGA LCD High Color Sun-Readable Touch Screen, Built-In Interfaces: 2XUSB; Ethernet; PS/2; Front Panel Sealed Keyboard and Mouse; sVGA output) > 100 250 VAC AC/DC converter SE 254064 PA - 64-Channel PA Pulsing Receiving and Processing Card: □ Up to 300 Volt Peak to Peak Bipolar Square Wave – Tunable Width / Tunable Firing Level Pulser; Special Probe Protection Circuit to Prevent Probe Damage for Not Properly Adjusted Pulse Width; Freely Adjustable Emitting Aperture - up to 64 elements simultaneous firing □ Analogue Gain: 0100 dB controllable in 0.5 dB resolution; Advanced Low Noise Design: 81µV peak to peak input referred to 80 dB gain / 25 MHz bandwidth; Frequency Band: 0.2 25 MHz Wide Band / 32-Taps FIR band pass digital filter with controllable lower and upper frequency limits; Freely Adjustable Receiving Aperture - up to 64 Elements, Parallel Analog to Digital Conversion - No Multiplexing Involved Ever Any Size of Paceiving Aperture 	<u>(Part #)</u> SA 804900	Standard Configuration # 1
	 For Any Size of Receiving Aperture Built-In Incremental Encoder Interface 		
	SE 254016/1 - 1-Channel UDS 3-6 Pulser Receiver Card		
	 □ Up to 400 V Peak to Peak Bipolar Square Wave – Tunable Width / Tunable Firing Level Pulser; Single / Dual Modes of Operation; Special Probe Protection Circuit to Prevent Probe Damage for Not Properly Adjusted Pulse Width □ Gain: 0100 dB controllable in 0.5 dB resolution; Advanced Low Noise Design: 81µV peak to peak input referred to 80 dB gain / 25 MHz bandwidth; Frequency Band: 0.2 25 MHz Wide Band / 32-Taps FIR band pass digital filter with controllable lower and upper frequency limits □ Built-In Incremental Encoder Interface 		
	• SW		
	 SVV ISONIC 2009 UPA-Scope Multi-Functional Package (SWA 99C09200) 		
	PA Modality		
	 ◆ PA Probes Database ⇒ Unlimitedly expandable database of PA probes - total aperture size, pitch and offset, wedge geometry and US Velocity / delay geometry and US Velocity, etc ⇒ Manual editing / update of PA probes, wedges and delays parameters or automatic importing of database from a file 		
	⇒ Exporting of PA probes / wedges / delays database into a file		
	 ◆ A-Scan ⇒ Manual control of emitting/receiving aperture, incidence angle, type of ultrasonic wave, focal distance / focal depth, etc ⇒ A-Scan (Full Wave / Neg Wave / Pos Wave rectification; RF) ⇒ True-To-Geometry Ray Trace (Focal Law) Visualization ⇒ DAC, TCG ⇒ Smart Automatic Measurements of Gated Signals - Flank / Flank First / Top / Top First; Auto-Marking Measuring Points on A-Scan ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ⇒ Generating Comprehensive Setup and A-Scan report 		

Item	Order Code (Part #)	Note
Cross-Sectional Scanning and Imaging:		
♦ ABI-Scan (B-Scan or E-Scan as per ASME Case 2558)		
➡ Linear electronically controlled scanning using predefined size of		
pulsing / receiving aperture, incidence angle, and type of ultrasonic wave		
within entire probe and automatic real time composing of True-To-		
Geometry B-Scan image with 100% raw data capturing		
➡ Unique Individual Gain per Incidence Point / Gain per Focal Law		
Adjustment to compensate:		
 inequality of PA probe elements 		
 variety of wedge losses 		
♦ Sector-Scan (S-Scan as per ASME Case 2557)		
Angular electronically controlled scanning using predefined pulsing /		
receiving aperture, and type of ultrasonic wave provided through steering		
of incidence angle and automatic real time composing of regular Sector		
Scan (S-Scan) or True-To-Geometry Sector-Scan (S-Scan) image with		
100% raw data capturing		
Angle Gain Compensation: Unique Individual Gain per Incidence		
Angle / Gain per Focal Law Adjustment compensating incidence		
angle-steering caused varieties of:		
 transparency for probe - material boundary 		
 wedge losses 		
 effective size of emitting/receiving aperture 		
Tandem B-Scan (Tandem B-Scan) - for 64 elements wedged		
probes only		
Unique electronically controlled Through-Thickness Shear Wave		
Scanning for Vertically Oriented Defects with automatically created		
focal laws and real time composing of True-To-Geometry Tandem B-		
Scan image with 100% raw data capturing		
Unique Individual Gain per Shot / Gain per Focal Law Adjustment		
compensating beam steering caused varieties of:		
 transparency for probe - material boundary 		
 wedge losses 		
 composition and actual/effective size of emitting and receiving 		
apertures		
All above modes of electronically controlled cross sectional scanning and imaging		
are featured with:		
➡ Freeze / Unfreeze of live image		
Live A-Scan for the selected beam of live / frozen image, smart signal evaluation using convertional acting of ultraconic signals		
signal evaluation using conventional gating of ultrasonic signals		
normalization, reject threshold, noise suppression, etc		
\Rightarrow Zoom In / Out		
Storing raw data image along with complete sequence of recorded		
A-Scans into a file		
➡ Upload raw data image from file		
 ⇒ Off-line image evaluation including: 		
 Sizing of defects – coordinates and projection size - gate based 		
and image based		
 Play-back and evaluation of A-Scans sourcing the image 		
 Echo-dynamic pattern analysis 		
 Defects outlining and pattern recognition based on A-Scan 		
sequence analysis		
Off-line reconstruction of the images for various Gain / Reject local		
DAC normalization		
➡ Generating Comprehensive Setup and Scanning Report		
Three-Dimensional Top - Side - End View Imaging Through Linear		
Scanning with PA Probes:		
ABI-Scan based C-Scan and 3D Data Presentation		
Sector-Scan based C-Scan and 3D Data Presentation		
Tandem B-Scan based C-Scan and 3D Data Presentation		
Control > Sector > Sect		
probe		
⇒ 3D presentation - Top, Side, End View		
SD presentation - rop, side, End view ⇒ Amplitude / Distance mode of C-Scan - Top View image		
Amplitude / Distance mode of C-scan - rop view image ⇒ Thickness Profiling / Flaw Detection presentation of Side / End View		
→ THICKNESS FTUILING / LIAW DELECTION PRESENTATION OF SIDE / END VIEW		

Item	Order Code (Part #)	Note
Storing raw 3D data comprising all raw data B-Scans each		
accompanied with complete sequence of recorded raw data A-Scans into		
a file		
 ⇒ Upload 3D data from a file ⇒ Comprehensive off-line analysis / postprocessing of 3D data featured 		
with:		
► 3D-Viewer		
 Off-line Recovery and Play-Back of A-Scans and Raw Data B- 		
Scans		
 Echo Dynamic Pattern Analysis; Sizing of defects – coordinates and projection size - gate based 		
and image based		
 Gate Manipulation - Rebuild Top, Side, End views for various 		
Gate Settings		
Off-line reconstruction of Top, Side, End views for various Gain / Deject level		
Reject level DAC normalization 		
 Slicing and Filtering Images 		
 Statistical Analysis 		
Generating Comprehensive Setup and Scanning Report		
Conventional UT Modality - Single Channel Operation		
♦ A-Scan		
A-Scan (Full Wave / Neg Wave / Pos Wave rectification; RF)		
Selectable A-Scan color scheme		
⇒ DAC, DGS, TCG		
Auto Calibration for Straight Beam and Angle Beam Probes Curved Surface (Well Thiskness (Skin Correction for Angle Beam)		
⇒ Curved Surface / Wall Thickness / Skip - Correction for Angle Beam Inspection		
Smart Automatic Measurements of Gated Signals - Flank / Flank		
First / Top / Top First; Auto-Marking Measuring Points on A-Scan		
⇒ FFT (Frequency Domain Signal Presentation) - additional feature for		
defects evaluation and / or pattern recognition / probes characterization ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including		
Gain Adjustments whilst in Freeze Mode		
Dual Ultrasound Velocity Multi-echo Measurements Mode		
⇒ Generating Comprehensive Setup and A-Scan / FFT graph report		
Pulse Echo Inspection, Recording, and Imaging Through Linear		
Scanning with Conventional Probes:		
Thickness Profile Imaging and Recording (Typical		
Application: Corrosion characterization)		
Continuous measuring of thickness value along probe trace and composing of Thickness Profile B-Scan with 100% raw data capturing		
 B-Scan cross-sectional imaging and recording of defects for 		
longitudinal and shear wave inspection		
Continuous measuring of echo amplitudes and reflectors coordinates		
along probe trace and composing of True-To-Geometry B-Scan with		
100% raw data capturing		
CB-Scan horizontal plane-view imaging and recording of		
defects for shear, surface, and guided wave inspection		
Continuous measuring of echo amplitudes and reflectors coordinates along probe trace and composing of True-To-Geometry CB-Scan with		
100% raw data capturing		
All above modes of linear scanning and imaging are featured with:		
Electromechanically encoded or time-based data recording		
⇒ Recording of complete sequence of A-Scans along scanning line		
Off-line evaluation of images featured with:		
Sizing of defects at any location along stored image – coordinates and projection size (plus remaining thickness, thickness, loss, and		
and projection size (plus remaining thickness, thickness loss, and length of damage for Thickness B-Scan);		
 Play-back and evaluation of A-Scans 		
Echo dynamic pattern analysis		
 Off-line reconstruction of image for various Gain / Gate setup 		
Generating Comprehensive Setup and Scanning Report		
Time of Flight Diffraction Technology - TOFD:		
		1
TOFD Inspection – RF B-Scan and D-Scan Imaging		
 TOFD Inspection – RF B-Scan and D-Scan Imaging Electromechanically encoded or time-based data recording 		
 ➡ Electromechanically encoded or time-based data recording ➡ Averaging recorded A-Scans 		
 ➡ Electromechanically encoded or time-based data recording ➡ Averaging recorded A-Scans ➡ Recording of complete sequence of A-Scans 		
 ➡ Electromechanically encoded or time-based data recording ➡ Averaging recorded A-Scans 		

#	Item	Order Code	Note
		(Part #)	
	 Linearization and straightening of TOFD Map Increasing contrast of TOFD images through varying Gain and 		
	rectification		
	 A-Scan sequence analysis 		
	 Defects pattern recognition and sizing with use of interactive parabolic cursors 		
	⇒ Generating Comprehensive Setup and Scanning Report		
	 Connectivity to Any Type of Windows Printer Through USB or LAN 		
	USB Flash Drive for External Data Storage		
	<u>12 months warranty period for the instrument</u>		
0	Lifetime free SW update	SA 804902	Standard Configuration #
	ISONIC 2009 UPA-Scope – Portable Digital Phased Array Ultrasonic Flaw Detector and Recorder: <i>64 channels PA</i>	SA 004902	Standard Configuration #
	electronics and 8 independent channels for connection of		
	conventional and TOFD probes		
	-		
	 ISONIC 2009 UPA-Scope Electronic unit > Internal PC (AMD LX 800 500 MHz, RAM-512M, Quazi-HDD Flash 		
	Memory Card 4G, Windows XP Embedded, Large 8.5" active TFT sVGA		
	LCD High Color Sun-Readable Touch Screen, Built-In Interfaces: 2XUSB;		
	Ethernet; PS/2; Front Panel Sealed Keyboard and Mouse; sVGA output)		
	 > 100 250 VAC AC/DC converter > SE 254064 PA - 64-Channel PA Pulsing Receiving and Processing Card: 		
	Up to 300 Volt Peak to Peak Bipolar Square Wave – Tunable Width /		
	Tunable Firing Level Pulser; Special Probe Protection Circuit to Prevent		
	Probe Damage for Not Properly Adjusted Pulse Width; Freely Adjustable Emitting Aperture - up to 64 elements simultaneous firing		
	 Analogue Gain: 0100 dB controllable in 0.5 dB resolution; 		
	Advanced Low Noise Design: 81µV peak to peak input referred to 80 dB		
	gain / 25 MHz bandwidth; Frequency Band: 0.2 25 MHz Wide Band /		
	32-Taps FIR band pass digital filter with controllable lower and upper frequency limits; Freely Adjustable Receiving Aperture - up to 64		
	Elements, Parallel Analog to Digital Conversion - No Multiplexing Involved		
	- For Any Size of Receiving Aperture		
	Built-In Incremental Encoder Interface		
	> SE 254016/1 - 1-Channel UDS 3-6 Pulser Receiver Card		
	Up to 400 V Peak to Peak Bipolar Square Wave – Tunable Width /		
	Tunable Firing Level Pulser; Single / Dual Modes of Operation; Special		
	Probe Protection Circuit to Prevent Probe Damage for Not Properly Adjusted Pulse Width		
	Gain: 0100 dB controllable in 0.5 dB resolution; Advanced Low		
	Noise Design: $81\mu V$ peak to peak input referred to 80 dB gain / 25 MHz		
	bandwidth; Frequency Band: 0.2 25 MHz Wide Band / 32-Taps FIR		
	 band pass digital filter with controllable lower and upper frequency limits Built-In Incremental Encoder Interface 		
	• SW ISONIC 2009 UPA-Scope Multi-Functional Package (SWA		
	99C09200)		
	PA Modality		
	♦ PA Probes Database		
	➡ Unlimitedly expandable database of PA probes - total aperture size,		
	pitch and offset, wedge geometry and US Velocity / delay geometry and US Velocity, etc		
	⇒ Manual editing / update of PA probes, wedges and delays		
	parameters or automatic importing of database from a file		
	Exporting of PA probes / wedges / delays database into a file		
	♦ A-Scan		
	Manual control of emitting/receiving aperture, incidence angle, type of ultrasonic wave, focal distance / focal depth, etc		
	So ultrasonic wave, local distance / local depin, etc So A-Scan (Full Wave / Neg Wave / Pos Wave rectification; RF)		
	⇒ True-To-Geometry Ray Trace (Focal Law) Visualization		
	⇒ DAC, TCG ⇒ Smort Automotic Macauramento of Cated Signala – Elank / Elank		
	Smart Automatic Measurements of Gated Signals - Flank / Flank First / Top / Top First; Auto-Marking Measuring Points on A-Scan		
	⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including		
	Gain Adjustments whilst in Freeze Mode		
1			1

Item	Order Code (Part #)	Note
Cross-Sectional Scanning and Imaging:	(
♦ ABI-Scan (B-Scan or E-Scan as per ASME Case 2558)		
Linear electronically controlled scanning using predefined size of		
pulsing / receiving aperture, incidence angle, and type of ultrasonic wave		
within entire probe and automatic real time composing of True-To-		
Geometry B-Scan image with 100% raw data capturing		
Unique Individual Gain per Incidence Point / Gain per Focal Law Adjustment to compensate:		
 inequality of PA probe elements 		
 variety of wedge losses 		
Sector-Scan (S-Scan as per ASME Case 2557)		
⇒ Angular electronically controlled scanning using predefined pulsing /		
receiving aperture, and type of ultrasonic wave provided through steering		
of incidence angle and automatic real time composing of regular Sector		
Scan (S-Scan) or True-To-Geometry Sector-Scan (S-Scan) image with 100% raw data capturing		
⇒ Angle Gain Compensation: Unique Individual Gain per Incidence		
Angle / Gain per Focal Law Adjustment compensating incidence		
angle-steering caused varieties of:		
 transparency for probe - material boundary 		
• wedge losses		
effective size of emitting/receiving aperture		
Tandem B-Scan (Tandem B-Scan) - for 64 elements wedged		
probes only		
Unique electronically controlled Through-Thickness Shear Wave Scanning for Vertically Oriented Defects with automatically created		
focal laws and real time composing of True-To-Geometry Tandem B-		
Scan image with 100% raw data capturing		
⇒ Unique Individual Gain per Shot / Gain per Focal Law Adjustment		
compensating beam steering caused varieties of:		
 transparency for probe - material boundary 		
 wedge losses 		
 composition and actual/effective size of emitting and receiving apertures 		
All above modes of electronically controlled cross sectional scanning and imaging		
are featured with:		
➡ Freeze / Unfreeze of live image		
⇒ Live A-Scan for the selected beam of live / frozen image, smart		
signal evaluation using conventional gating of ultrasonic signals		
⇒ Versatile user configurable color palette for defects imaging, DAC parmalization relatification price guarantee at a second parmalization.		
normalization, reject threshold, noise suppression, etc		
Storing raw data image along with complete sequence of recorded		
A-Scans into a file		
➡ Upload raw data image from file		
→ Off-line image evaluation including:		
Sizing of defects – coordinates and projection size - gate based		
and image based		
Play-back and evaluation of A-Scans sourcing the image Economic pattern analysis		
 Echo-dynamic pattern analysis Defects outlining and pattern recognition based on A-Scan 		
sequence analysis		
 Off-line reconstruction of the images for various Gain / Reject 		
level		
 DAC normalization 		
Generating Comprehensive Setup and Scanning Report		
Three-Dimensional Top - Side - End View Imaging Through Linear		
Scanning with PA Probes:		
ABI-Scan based C-Scan and 3D Data Presentation		
Sector-Scan based C-Scan and 3D Data Presentation		
Tandem B-Scan based C-Scan and 3D Data Presentation		
➡ Electromechanically encoded or time-based line scanning with PA		
probe		
⇒ 3D presentation - Top, Side, End View		
Amplitude / Distance mode of C-Scan - Top View image Thickness Profiling / Elew Detection presentation of Side / End View		
 Thickness Profiling / Flaw Detection presentation of Side / End View Storing raw 3D data comprising all raw data B-Scaps each 		
Storing raw 3D data comprising all raw data B-Scans each accompanied with complete sequence of recorded raw data A-Scans into		
a file		
➡ Upload 3D data from a file		

#	ltem	Order Code (Part #)	Note
	Comprehensive off-line analysis / postprocessing of 3D data featured with:		
	→ 3D-Viewer		
	 Off-line Recovery and Play-Back of A-Scans and Raw Data B- Scans 		
	 Echo Dynamic Pattern Analysis; 		
	 Sizing of defects – coordinates and projection size - gate based 		
	and image based ► Gate Manipulation - Rebuild Top, Side, End views for various		
	Gate Settings		
	 Off-line reconstruction of Top, Side, End views for various Gain / Reject level 		
	► DAC normalization		
	 Slicing and Filtering Images Statistical Analysis 		
	 Generating Comprehensive Setup and Scanning Report 		
	Conventional UT Modality - Single and Multi Channel		
	Operation		
	◆ A-Scan		
	 A-Scan (Full Wave / Neg Wave / Pos Wave rectification; RF) ⇒ Selectable A-Scan color scheme 		
	⇒ DAC, DGS, TCG		
	 Auto Calibration for Straight Beam and Angle Beam Probes ⇒ Curved Surface / Wall Thickness / Skip - Correction for Angle Beam 		
	Inspection		
	Smart Automatic Measurements of Gated Signals - Flank / Flank First / Top / Top First; Auto-Marking Measuring Points on A-Scan		
	SFT (Frequency Domain Signal Presentation) - additional feature for		
	defects evaluation and / or pattern recognition / probes characterization		
	Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode		
	⇒ Dual Ultrasound Velocity Multi-echo Measurements Mode		
	➡ Generating Comprehensive Setup and A-Scan / FFT graph report Pulse Echo Inspection, Recording, and Imaging Through Linear		
	Scanning with Conventional Probes – Single Channel Operation:		
	Thickness Profile Imaging and Recording (Typical		
	Application: Corrosion characterization)		
	composing of Thickness Profile B-Scan with 100% raw data capturing		
	B-Scan cross-sectional imaging and recording of defects for		
	longitudinal and shear wave inspection		
	along probe trace and composing of True-To-Geometry B-Scan with		
	100% raw data capturing		
	CB-Scan horizontal plane Top-View imaging and recording of defects for shear, surface, and guided wave inspection		
	➡ Continuous measuring of echo amplitudes and reflectors coordinates		
	along probe trace and composing of True-To-Geometry CB-Scan with 100% raw data capturing		
	All above modes of linear scanning and imaging are featured with:		
	➡ Electromechanically encoded or time-based data recording		
	 ⇒ Recording of complete sequence of A-Scans along scanning line ⇒ Off-line evaluation of images featured with: 		
	 Sizing of defects at any location along stored image – coordinates 		
	and projection size (plus remaining thickness, thickness loss, and		
	length of damage for Thickness B-Scan); ▶ Play-back and evaluation of A-Scans		
	 Echo dynamic pattern analysis 		
	 Off-line reconstruction of image for various Gain / Gate setup Generating Comprehensive Setup and Scanning Reporting 		
	Time of Flight Diffraction Technology – TOFD – Single Channel		
	Operation:		
	 TOFD Inspection – RF B-Scan and D-Scan Imaging Electromechanically encoded or time-based data recording 		
	 ⇒ Electromechanically encoded or time-based data recording ⇒ Averaging recorded A-Scans 		
	⇒ Recording of complete sequence of A-Scans		
	 Off-line evaluation of TOFD Map featured with: Improving near to surface resolution through removal of lateral 		
	wave and back echo records from TOFD Map		
	Linearization and straightening of TOFD Map		

#	Item	Order Code (Part #)	Note
	 Increasing contrast of TOFD images through varying Gain and rectification A-Scan sequence analysis Defects pattern recognition and sizing with use of interactive parabolic cursors Generating Comprehensive Setup and Scanning Report Multi-Channel Operation – up to 8 channels for Conventional and 		
	TOFD Probes		
	♦ Multiple A-Scan		
	 Strip Chart Continuous capturing and recording of up to 8 channel complete sequence A-Scans along probe trace and real time creating of up to 8 channel strip chart 		
	Time-based (real time clock) and true-to-location (built-in incremental encoder interface) modes of data recording		
3	 4 types of strip chart selectable by operator: ∇ TOFD Map PE Amplitude / TOF Coupling Comprehensive Off-line evaluation of recorded strip chart: Play-back and evaluation of A-Scans Marking Defects and Creating Defect List Varying layout of strip chart Conversion of Map Strips into PE Amplitude TOF strips and reverse conversion of PE Amplitude TOF strips into Map Strips Varying ROI and rebuild of PE Amplitude/TOF Strips Varying ROI and rebuild of PE Amplitude/TOF Strips Stripped C-Scan Creation Echo dynamic pattern analysis Individual Postprocessing of Each strip based on strip type: TOFD Map PE Amplitude / TOF Generating Comprehensive Setup and Scanning Report <u>USB Flash Drive for External Data Storage</u> <u>12 months warranty period for the instrument</u> Lifetime free SW update ISONIC 2009 UPA-Scope – Portable Digital Phased Array 	SA 804906	Customized Configuration
	Ultrasonic Flaw Detector and Recorder: 64 channels PA electronics and 16 independent channels for connection of conventional and TOFD probes	04 004000	- to be agreed on order
4	Rechargeable Battery Ni MH 9 AH / 12V	SK 2005102	Optional
5	Battery Charger	SK 2005103	Optional Required for battery charge
6	Silicon Rubber Jacket	SK 2009111	Optional
7	Travel Hard Case	SK 2009104	Optional Allows safe cargo transportation

#	Item	Order Code (Part #)	Note
8	Postprocessing SW Package for Office PC: ISONIC 2009 PP ⇔ comprehensive postprocessing of inspection results PA Modality files captured by ISONIC 2009 UPA-Scope using Inspection SW Packages of any type ⇔ automatic creating of ISONIC 2009 UPA-Scope - PA Modality inspection reports for printing hard copy	2009 PP SWA 909844 Included into sc supply of each I ty files captured by pe 2009 UPA Scop	
9	Wheels-Free Compact One-Axis Mechanical Encoder for manual line scanning with PA probes and for TOFD / CHIME/ CB-Scan / Thickness Profile / Straight Beam B-Scan imaging with conventional probes	SK 2001108 PA	Optional
10	Inspection SW Utility for ISONIC 2009 UPA-Scope - PA Modality: KIs - Delta Technique ⇒ Single probe insonification of defects with receiving and evaluation of direct and mode converted echoes for the distinguishing between volumetric and sharp defects ⇒ Generating Comprehensive Setup and Evaluation Report	SWA 909801	Optional
11	Inspection SW Utility for ISONIC 2009 UPA-Scope - PA Modality: CDM - Crack Depth Measurements ⇒ Single probe sizing of cracks and remaining wall thickness ⇒ Generating Comprehensive Setup and Evaluation Report	SWA 909802	Optional
12	Inspection SW Package for ISONIC 2009 UPA-Scope - PA Modality: Horizontal Plane Top View CB-Scan - Lateral Scanning Scanning Technique # 1 Electronically controlled scanning using predefined pulsing / receiving aperture and type of ultrasonic wave provided through swiveling of ultrasonic beam with predefined incidence angle and automatic real time composing of Top View CB-Scan image with 100% raw data capturing Swiveling Angle Gain Compensation: Unique Individual Gain per Swiveling Angle / Gain per Focal Law Adjustment compensating swiveling angle-steering caused varieties of: wedge losses effective size of emitting/receiving aperture Electronically controlled scanning using predefined size of pulsing / receiving aperture, incidence and swiveling angle, and type of ultrasonic wave through linear motion of ultrasonic beam within entire probe and automatic real time composing of Top View CB-Scan image with 100% raw data capturing Unique Individual Gain per Incidence Point / Gain per Focal Law Adjustment to compensate: inequality of PA probe elements Both electronically controlled scanning techniques are featured with: Freeze / Unfreeze of live image Live A-Scan for the selected beam of live / frozen image, smart signal evaluation using conventional gating of ultrasonic signals Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc Zoom In / Out Stor	SWA 909803	Optional
13	 ► DAC normalization ➡ Generating Comprehensive Setup and Scanning Report Inspection SW Package for ISONIC 2009 UPA-Scope - PA Modality: EXPERT - Weld Inspection (planar and circumferential butt welds, nozzle welds, fillet welds) Cross-Sectional Scanning and Imaging Uniquely Representing Real 	SWA 909804	Optional
	Distribution Of Ultrasonic Beams In the Weld and Parent Material with True- To-Location Visualization of Defects and Weld Geometry: ◆ ABI-Scan (B-Scan or E-Scan as per ASME Case 2558) ⇒ Linear electronically controlled scanning using predefined size of pulsing / receiving aperture, incidence angle, and type of ultrasonic wave within entire probe and automatic real time composing of True-To-Geometry B-Scan image with 100% raw data capturing ⇒ Unique Individual Gain per Incidence Point / Gain per Focal Law Adjustment to compensate: ● inequality of PA probe elements ● variety of wedge losses		

ŧ	Item	Order Code (Part #)	Note
	♦ Sector-Scan (S-Scan as per ASME Case 2557)	(1 art #)	
	 Angular electronically controlled scanning using predefined pulsing / receiving aperture, and type of ultrasonic wave provided through steering of incidence angle and automatic real time composing of regular Sector Scan (S-Scan) or True-To-Geometry Sector-Scan (S-Scan) image with 100% raw data capturing Angle Gain Compensation: Unique Individual Gain per Incidence Angle / Gain 		
	 per Focal Law Adjustment compensating incidence angle-steering caused varieties of: transparency for probe - material boundary 		
	 wedge losses effective size of emitting/receiving aperture 		
	Both modes of electronically controlled cross sectional scanning are featured with: ⇒ Freeze / Unfreeze of live image ⇒ Live A-Scan for the selected beam of live / frozen image, smart signal evaluation		
	using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc		
	 ➡ Zoom In / Out ➡ Storing raw data image along with complete sequence of recorded A-Scans into a file 		
	➡ Upload raw data image from file		
	 Off-line image evaluation including: Sizing of defects – coordinates and projection size - gate based and image based 		
	 Play-back and evaluation of A-Scans sourcing the image Echo-dynamic pattern analysis 		
	 Defects outlining and pattern recognition based on A-Scan sequence analysis Off-line reconstruction of the images for various Gain / Reject level DAC normalization Generating Comprehensive Setup and Scanning Report 		
	<u>Three-Dimensional Top - Side - End View Imaging of Weld and Heat</u> Affected Zone Through Linear Scanning with PA Probes:		
	♦ ABI-Scan based C-Scan and 3D Data Presentation		
	 ♦ Sector-Scan based C-Scan and 3D Data Presentation ⇒ Electromechanically encoded or time-based line scanning with PA probe ⇒ 3D presentation - Top, Side, End View ⇒ Amplitude (Distance media of C Scan, Tap View impage) 		
	 Amplitude / Distance mode of C-Scan - Top View image Thickness Profiling / Flaw Detection presentation of Side / End View Storing raw 3D data comprising all raw data B-Scans each accompanied with complete sequence of recorded raw data A-Scans into a file 		
	 ➡ Upload 3D data from a file ➡ Comprehensive off-line analysis / postprocessing of 3D data featured with: ▲ 3D-Viewer 		
	 Off-line Recovery and Play-Back of A-Scans and Raw Data B-Scans Echo Dynamic Pattern Analysis; Sizing of defects – coordinates and projection size - gate based and image based 		
	 Gate Manipulation - Rebuild Top, Side, End views for various Gate Settings Off-line reconstruction of Top, Side, End views for various Gain / Reject level DAC normalization 		
	 Slicing and Filtering Images Statistical Analysis 		
4	Generating Comprehensive Setup and Scanning Reporting	SWA 909805	Optional
4	Inspection SW Package for ISONIC 2009 UPA-Scope - PA Modality: EXPERT CU - Weld Inspection (longitudinal welds in tubes; nozzle, fillet, TKY, etc welds for curved components) Cross-Sectional Scanning and Imaging Uniquely Representing Real	SWA 909003	Optional
	Distribution Of Ultrasonic Beams In the Weld and Parent Material with True- To-Location Visualization of Defects and Weld Geometry:		
	 ♦ Sector-Scan (S-Scan as per ASME Case 2557) ⇒ Angular electronically controlled scanning using predefined pulsing / receiving 		
	aperture, and type of ultrasonic wave provided through steering of incidence angle and automatic real time composing of regular Sector Scan (S-Scan) or True-To-Geometry Sector-Scan (S-Scan) image with 100% raw data capturing ⇒ Angle Gain Compensation: Unique Individual Gain per Incidence Angle / Gain per Focal Law Adjustment compensating incidence angle-steering caused varieties of:		
	 transparency for probe - material boundary wedge losses effective size of emitting/receiving aperture 		
	 ⇒ Freeze / Unfreeze of live image ⇒ Live A-Scan for the selected beam of live / frozen image, smart signal evaluation using conventional gating of ultrasonic signals 		
	 ▷ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc ▷ Zoom In / Out ▷ Storing raw data image along with complete sequence of recorded A-Scans into a 		
	file ⇔ Upload raw data image from file		

#	Item	Order Code (Part #)	Note
	 ⇔ Off-line image evaluation including: Sizing of defects – coordinates and projection size - gate based and image based Play-back and evaluation of A-Scans sourcing the image Echo-dynamic pattern analysis Defects outlining and pattern recognition based on A-Scan sequence analysis Off-line reconstruction of the images for various Gain / Reject level DAC normalization ⇔ Generating Comprehensive Setup and Scanning Report Three-Dimensional Top - Side - End View Imaging of Weld and Heat Affected Zone Through Linear Scanning with PA Probes: ♦ Sector-Scan based C-Scan and 3D Data Presentation ⇒ Electromechanically encoded or time-based line scanning with PA probe ⇒ 3D presentation - Top, Side, End View ⇒ Amplitude / Distance mode of C-Scan - Top View image ⇒ Thickness Profiling / Flaw Detection presentation of Side / End View ⇒ Storing raw 3D data comprising all raw data B-Scans each accompanied with complete sequence of recorded raw data A-Scans and Raw Data Bescans ⇒ Echo Dynamic Pattern Analysis; > Sizing of defects – coordinates and projection size - gate based and image based > Gate Manipulation - Rebuild Top, Side, End views for various Gate Settings > Off-line reconstruction of Top, Side, End views for various Gain / Reject level > DAC normalization > Slicing and Filtering Images 		
15	 Generating Comprehensive Setup and Scanning Report Inspection SW Package for ISONIC 2009 UPA-Scope - PA Modality: VLFS - Vertical Line Focusing Scanning and Imaging (typical application: inspection of planar and circumferential ER welds, welded rails, etc) Cross-Sectional Scanning and Imaging Uniquely Representing Real Distribution Of Ultrasonic Beams In the Selected Region of Interest (ROI) with True-To-Location Visualization of Defects: ABI-Scan (B-Scan or E-Scan as per ASME Case 2558) Linear electronically controlled scanning using predefined size of pulsing / receiving aperture, incidence angle, and type of ultrasonic wave within entire probe and automatic real time composing of True-To-Geometry B-Scan image with 100% raw data capturing 	SWA 909806	Optional
	 ⇒ Unique Individual Gain per Incidence Point / Gain per Focal Law Adjustment to compensate: inequality of PA probe elements variety of wedge losses ◆ Sector-Scan (S-Scan as per ASME Case 2557) ⇒ Angular electronically controlled scanning using predefined pulsing / receiving aperture, and type of ultrasonic wave provided through steering of incidence angle and automatic real time composing of regular Sector Scan (S-Scan) or True-To-Geometry Sector-Scan (S-Scan) image with 100% raw data capturing ⇒ Angle Gain Compensation: Unique Individual Gain per Incidence Angle / Gain per Focal Law Adjustment compensating incidence angle-steering caused varieties of: transparency for probe - material boundary wedge losses effective size of emitting/receiving aperture Both modes of electronically controlled cross sectional scanning are featured with: Freeze / Unfreeze of live image Live A-Scan for the selected beam of live / frozen image, smart signal evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc ≥ Zoom In / Out ⇒ Storing raw data image from file ⇒ Off-line image evaluation including: Sizing of defects – coordinates and projection size - gate based and image based Play-back and evaluation of A-Scans sourcing the image Echo-dynamic pattern recognition based on A-Scan sequence analysis > Defects outlining and pattern recognition based on A-Scan sequence analysis > Off-line reconstruction of the images for various Gain / Reje		

ŧ	Item	Order Code (Part #)	Note
٦	Three-Dimensional Top - Side - End View Imaging of Weld and Heat		
	Affected Zone Through Linear Scanning with PA Probes:		
	 ABI-Scan based C-Scan and 3D Data Presentation Sector-Scan based C-Scan and 3D Data Presentation 		
	Sector-Scan based C-Scan and 3D bata Presentation ⇒ Electromechanically encoded or time-based line scanning with PA probe		
	 ⇒ 3D presentation - Top, Side, End View 		
	Amplitude / Distance mode of C-Scan - Top View image		
	Thickness Profiling / Flaw Detection presentation of Side / End View		
	Storing raw 3D data comprising all raw data B-Scans each accompanied with complete sequence of recorded raw data A-Scans into a file		
	 ⇒ Upload 3D data from a file ⇒ Comprehensive off-line analysis / postprocessing of 3D data featured with: > 3D-Viewer 		
	 Off-line Recovery and Play-Back of A-Scans and Raw Data B-Scans Echo Dynamic Pattern Analysis; 		
	 Sizing of defects – coordinates and projection size - gate based and image based 		
	 Gate Manipulation - Rebuild Top, Side, End views for various Gate Settings Off-line reconstruction of Top, Side, End views for various Gain / Reject level DAC normalization Slicing and Filtering Images 		
	 Statistical Analysis 		
	Generating Comprehensive Setup and Scanning Report		
6	Inspection SW Package for ISONIC 2009 UPA-Scope - PA Modality:	SWA 909807	Optional
	VLFS CU – Vertical Line Focusing Scanning and Imaging of		
	Tubular Objects (typical application: inspection of longitudinal		
	ERW in tubes and similar objects)		
	Cross-Sectional Scanning and Imaging Uniquely Representing Real		
	Distribution Of Ultrasonic Beams In the Selected Region of Interest (ROI)		
	with True-To-Location Visualization of Defects:		
	♦ Sector-Scan (S-Scan as per ASME Case 2557)		
	Angular electronically controlled scanning using predefined pulsing / receiving		
	aperture, and type of ultrasonic wave provided through steering of incidence angle and automatic real time composing of regular Sector Scan (S-Scan) or True-To-Geometry		
	Sector-Scan (S-Scan) image with 100% raw data capturing		
	 Angle Gain Compensation: Unique Individual Gain per Incidence Angle / Gain per Focal Law Adjustment compensating incidence angle-steering caused varieties of: transparency for probe - material boundary 		
	● wedge losses		
	 effective size of emitting/receiving aperture 		
	⇒ Freeze / Unfreeze of live image		
	Live A-Scan for the selected beam of live / frozen image, smart signal evaluation using conventional gating of ultrasonic signals		
	➡ Versatile user configurable color palette for defects imaging, DAC normalization,		
	reject threshold, noise suppression, etc		
	 Storing raw data image along with complete sequence of recorded A-Scans into a 		
	file		
	⇒ Upload raw data image from file		
	➡ Off-line image evaluation including:		
	 Sizing of defects – coordinates and projection size - gate based and image 		
	 Play-back and evaluation of A-Scans sourcing the image 		
	 Echo-dynamic pattern analysis 		
	Defects outlining and pattern recognition based on A-Scan sequence analysis		
	 Off-line reconstruction of the images for various Gain / Reject level 		
	 DAC normalization 		
	Generating Comprehensive Setup and Scanning Report		
	Three-Dimensional Top - Side - End View Imaging of Weld and Heat		
	Affected Zone Through Linear Scanning with PA Probes:		
	Sector-Scan based C-Scan and 3D Data Presentation		
	 ⇒ Electromechanically encoded or time-based line scanning with PA probe ⇒ 3D presentation - Top, Side, End View 		
	⇒ Amplitude / Distance mode of C-Scan - Top View image		
	⇒ Thickness Profiling / Flaw Detection presentation of Side / End View		
	Storing raw 3D data comprising all raw data B-Scans each accompanied with complete sequence of recorded raw data A-Scans into a file		
	 ⇒ Upload 3D data from a file ⇒ Comprehensive off-line analysis / postprocessing of 3D data featured with: 		
	 3D-Viewer Off-line Recovery and Play-Back of A-Scans and Raw Data B-Scans 		
	 Echo Dynamic Pattern Analysis; Sizing of defects – coordinates and projection size - gate based and image 		
	 based Gate Manipulation - Rebuild Top, Side, End views for various Gate Settings 		
	Gate Manipulation - Rebuild Top, Side, End views for various Gate Settings		

#	ltem	Order Code	Note
ir –	Kom	(Part #)	1010
	 Off-line reconstruction of Top, Side, End views for various Gain / Reject level DAC parameters 	. ,	
	 DAC normalization Slicing and Filtering Images 		
	 Statistical Analysis 		
17	Generating Comprehensive Setup and Scanning Report	SWA 909808	Optional
17	Inspection SW Utility for ISONIC 2009 UPA-Scope - PA Modality: 3D- SCAN L – Longitudinal Wave Insonification of the Material with	SWA 909606	Optional
	Use of Matrix Array Probe and Composing 3D Image in Real Time		
	♦ 3D L A-Scan		
	Unique manual control of emitting/receiving aperture within entirely connected matrix array probe, incidence angle, beam rotation angle, focal distance / focal depth.		
	etc for longitudinal wave		
	A-Scan (Full Wave / Neg Wave / Pos Wave rectification; RF)		
	➡ True-To-Geometry Ray Trace (Focal Law) 3D Visualization ➡ DAC, TCG		
	Smart Automatic Measurements of Gated Signals - Flank / Flank First / Top / Top First Auto Marking Measuring Daints on A Second		
	First; Auto-Marking Measuring Points on A-Scan		
	Adjustments whilst in Freeze Mode		
	 ◆ 3D-Scan L ⇒ Electronically controlled longitudinal wave scanning of predefined volume in the 		
	material using matrix array probe and real time composing of 3D-image (3D-Scan) of		
	object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image		
	⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal		
	evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization,		
	reject threshold, noise suppression, etc		
	 ⇒ 3D-Viewing manipulator for live/frozen 3D image ⇒ Zoom In / Out 		
	Storing 3D-image along with complete sequence of recorded A-Scans (raw data)		
	into a file ⇒ Upload 3D-image with raw data from a file		
	➡ Off-line image evaluation including:		
	 Sizing of defects – coordinates and projection size - gate based and image based 		
	 Play-back and evaluation of A-Scans sourcing the image 		
	 Echo-dynamic pattern analysis Defects outlining and pattern recognition based on A-Scan sequence analysis 		
	 Off-line reconstruction of the images for various Gain / Reject level 		
	 DAC normalization Generating Comprehensive Setup and Scanning Report 		
18	Inspection SW Utility for ISONIC 2009 UPA-Scope - PA Modality: 3D-	SWA 909809	Optional
	SCAN S – Shear Wave Insonification of the Material with Use of		
	Matrix Array Probe and Composing 3D Image in Real Time		
	 ◆ 3D S A-Scan ⇒ Unique manual control of emitting/receiving aperture within entirely connected 		
	matrix array probe, incidence angle, beam rotation angle, focal distance / focal depth,		
	etc for shear wave ⇔ A-Scan (Full Wave / Neg Wave / Pos Wave rectification; RF)		
	➡ True-To-Geometry Ray Trace (Focal Law) 3D Visualization		
	 ⇒ DAC, TCG ⇒ Smart Automatic Measurements of Gated Signals - Flank / Flank First / Top / Top 		
	First; Auto-Marking Measuring Points on A-Scan		
	Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material 		
	 Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode 3D-Scan S 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image ⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image ⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal evaluation using conventional gating of ultrasonic signals 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image ⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc ⇒ 3D-Viewing manipulator for live/frozen 3D image ⇒ Zoom In / Out 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image ⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc ⇒ 3D-Viewing manipulator for live/frozen 3D image 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image ⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc ⇒ 3D-Viewing manipulator for live/frozen 3D image ⇒ Zoom In / Out ⇒ Storing 3D-image along with complete sequence of recorded A-Scans (raw data) into a file ⇒ Upload 3D-image with raw data from a file 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image ⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc ⇒ 3D-Viewing manipulator for live/frozen 3D image ⇒ Zoom In / Out ⇒ Storing 3D-image along with complete sequence of recorded A-Scans (raw data) into a file ⇒ Upload 3D-image with raw data from a file ⇒ Off-line image evaluation including: 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image ⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc ⇒ 3D-Viewing manipulator for live/frozen 3D image ⇒ Zoom In / Out ⇒ Storing 3D-image along with complete sequence of recorded A-Scans (raw data) into a file ⇒ Off-line image evaluation including: > Sizing of defects – coordinates and projection size - gate based and image based 		
	 ⇒ Enhanced Signal Evaluation for Live and Frozen A-Scans including Gain Adjustments whilst in Freeze Mode ◆ 3D-Scan S ⇒ Electronically controlled shear wave scanning of predefined volume in the material using matrix array probe and real time composing of 3D-image (3D-Scan) of object under test with 100% raw data capturing ⇒ Freeze / Unfreeze of live 3D image ⇒ Live A-Scan for the selected beam of live / frozen 3D image, smart signal evaluation using conventional gating of ultrasonic signals ⇒ Versatile user configurable color palette for defects imaging, DAC normalization, reject threshold, noise suppression, etc ⇒ 3D-Viewing manipulator for live/frozen 3D image ⇒ Zoom In / Out ⇒ Storing 3D-image along with complete sequence of recorded A-Scans (raw data) into a file ⇒ Upload 3D-image with raw data from a file ⇒ Off-line image evaluation including: > Sizing of defects – coordinates and projection size - gate based and image 		

#	Item	Order Code (Part #)	Note
	 Off-line reconstruction of the images for various Gain / Reject level DAC normalization Generating Comprehensive Setup and Scanning Report 		
19	Inspection SW Utility for ISONIC 2009 UPA-Scope - PA Modality: Multi- Group – Implementation of Several (up to 5) Various Insonification Schemes Simultaneously with Use of Differently Configured Groups of Elements of Wedged Linear Array Probe	SWA 909810	
20	Postprocessing SW Package for Office PC: ISONIC PA PP – ⇔ comprehensive postprocessing of inspection results files captured by ISONIC 2009 UPA-Scope and ISONIC 2010 - PA Modality using Inspection SW Packages of any type ⇔ automatic creating of inspection reports	SWA909844	Delivered with every ISONIC 2009 UPA Scope instrument
21	Postprocessing SW Package for Office PC: ISONIC PA ABIScan Puzzle composing PUZZLE file comprising raw data from several ABIScan based top view scanning files providing large area coverage with/without overlap comprehensive off-line analysis / postprocessing of 3D PUZZLE data featured with: Top, Side, End Puzzle Composed Views of Large Area 3D-Viewer Off-line Recovery and Play-Back of A-Scans Echo Dynamic Pattern Analysis; Sizing of defects – coordinates and projection size - gate based and image based Gate Manipulation - Rebuild Top, Side, End views for various Gate Settings Off-line reconstruction of Top, Side, End views for various Gain / Reject level DAC normalization Slicing and Filtering Images Statistical Analysis generating comprehensive Setup and Scanning Report 	SWA 909845	Option
22	Postprocessing SW Package for Office PC: IOFFICE - ISONIC Office ⇒ comprehensive postprocessing of inspection results files captured by ISONIC 2001, ISONIC 2005, ISONIC 2007, ISONIC 2008, ISONIC 2009 UPA-Scope, ISONIC 2010 instruments using conventional and TOFD probes and Inspection SW Packages of any type ⇒ generating comprehensive inspection reports in MS Word® format	SWA99C0203	Optional
23	Dual Channel TOFD preamplifier package including: ⇒ Dual Channel TOFD preamplifier ⇒ Set of 2 low noise coaxial cables (10 meters length each) for connection to the signal input of ISONIC instrument	SA 80442	Optional Improves long cable connection to conventional and TOFD ultrasonic probes
24	ISONIC Alarmer - standard firmware configuration and hardware platform including:	SE 554780987	Optional
25	Set of test blocks for phased array inspection; material - low carbon steel	S 8001 PA	See photos below
26	Set of test blocks for phased array inspection; material - stainless steel ASTM 304	S 8001ASTM304 See photos below PA	
27	Set of test blocks for phased array inspection; material - stainless steel ASTM 316	S 8001ASTM316 PA	See photos below
28	Ultrasonic PA, conventional, and TOFD probes, fixtures, scanners, cables and other accessories depending on the inspection tasks to be resolved		Optional

()

Information about typical PA probes, wedges, delay lines is available in the chapters 5.3.1, 5.4, 5.5.2.5 of this Operating Manual

1

S 8001 PA, S 8001ASTM304 PA, and S 8001ASTM316 PA sets consist of two blocks each made of low carbon steel, stainless steel ASTM 304, and stainless steel ASTM 316 correspondingly Block # 1





Block # 2







4. Operating ISONIC 2009

Please read the following information before you use **ISONIC 2009 UPA-Scope**. It is essential to read and understand the following information so that no errors occur during operation, which could lead damaging of the unit or misinterpretation of inspection results

4.1. Preconditions for ultrasonic testing with ISONIC 2009 UPA-Scope

Operator of **ISONIC 2009 UPA-Scope** must be certified as at least *Level 2 Ultrasonic Examiner* additionally having the adequate knowledge of

- operating digital ultrasonic flaw detector
- basics of computer operating in the **Windows™** environment including turning computer on/off, keyboard, touch screen and mouse, starting programs, saving and opening files

4.2. ISONIC 2009 Controls and Terminals

Item	Order Code (Part #)	Note
ISONIC 2009 UPA-Scope – Portable Digital Phased Array Ultrasonic Flaw Detector and Recorder: 64 channels PA electronics and 1 independent channel for connection of conventional and TOFD probes		Standard Configuration # 1





Terminal for Connection to PA Probe

Probe Terminal	Pulser Mode: Dual	Pulser Mode: Single
Black	Receiver Input	Firing Output / Receiver Input
White	Firing Output	Not Used

Item	Order Code (Part #)	Note
ISONIC 2009 UPA-Scope – Portable Digital Phased Array Ultrasonic Flaw Detector and Recorder: 64 channels PA electronics and 8 independent channels for connection of conventional and TOFD probes	SA 804902	Standard Configuration # 2



Probe Terminal	UDS 3-6 Pulser	Pulser Mode:	Pulser Mode:
	Receiver Channel #	Dual	Single
1-1	1	Receiver Input	Firing Output / Receiver Input
2-1	1	Firing Output	Not Used
1-2	2	Receiver Input	Firing Output / Receiver Input
2-2	2	Firing Output	Not Used
1-3	3	Receiver Input	Firing Output / Receiver Input
2-3	3	Firing Output	Not Used
1-4	4	Receiver Input	Firing Output / Receiver Input
2-4	4	Firing Output	Not Used
1-5	5	Receiver Input	Firing Output / Receiver Input
2-5	5	Firing Output	Not Used
1-6	6	Receiver Input	Firing Output / Receiver Input
2-6	6	Firing Output	Not Used
1-7	7	Receiver Input	Firing Output / Receiver Input
2-7	7	Firing Output	Not Used
1-8	8	Receiver Input	Firing Output / Receiver Input
2-8	8	Firing Output	Not Used




4.3. Turning On / Off

ISONIC 2009 UPA Scope may be powered from:

- 100...250 VAC through external AC/DC converter
- External 11...16V DC source (12V typical)
- Rechargeable battery (optionally)

AC Power Supply

- □ Ensure that power switch is in **O** position before connecting power cords
- Connect one end of AC power cord to AC/DC converter and plug another end into AC mains
- Connect DC power cord with suppression filter outgoing from AC/DC converter to DC Supply Voltage Input of ISONIC 2009 UPA Scope

External DC Power Supply

- Ensure DC mains do supply voltage between 11 V and 16 V
- Ensure that power switch is in **O** position before connecting power cord
- Connect one end of DC power cord with suppression filter to DC Supply Voltage Input of ISONIC 2009 UPA Scope and plug another end into DC mains

Battery

- □ Ensure that power switch is in **O** position
- □ Plug in battery and fix it using 4 screws

Power-Up and Turn Off

To Power-Up **ISONIC 2009 UPA Scope** set power switch into **I** position. An automatic system test program will then be executed; during this test various texts and information appear followed by the screen as below while booting up



Wait until **ISONIC 2009 UPA Scope Start Screen** becomes active automatically upon boot up is completed



Click on constraints or press F1 to run PA modality – refer to Chapter 5 of this Operating Manual
Click on or press F2 to operate instruments with conventional and TOFD probes – refer to Chapter 6 of this Operating Manual
Click on Or press F3 to proceed with Windows XP Embedded settings of ISONIC 2009 UPA-Scope instrument, such as for example setting up drivers for external devices (printers, USB memory card, and the like), connecting to LAN, quasi-disk management, etc – refer to paragraph 8.4 of this Operating Manual
To turn ISONIC 2009 off click on Isometry or press F4 then wait until the screen as below appears:
Microsoft" Windows" It's new safe to turn off your computer.

Set power switch into **O** position upon

After turning ISONIC 2009 UPA-Scope OFF wait at least 10...30 seconds before switching it ON again

5. PA Modality

5.1. PA Modality Start Menu

The screen as below appears on selecting to run ISONIC 2009 UPA Scope in PA modality

	1 Operate	51
	2 Settings	
	3 Postprocessing	
	4 Back	
Click on I operate or press	s F1 to start operation	
Click on Settings or press	s F2 to proceed with instrument settings	
Click on 3 Postprocessing or press inspection files captured while ru	s F3 to open instrument's explorer allow nning PA modality	ing uploading of all setup and
Click on Back or press	s F4 or Esc to return to ISONIC 2009 L	IPA-Scope Start Screen

5.2. Standard and Optional Modes Of Operation

The following screen appears upo paragraph 5.1 of this Operating M		n the PA modality start menu as per	
	1 Wedge 2 Delay Line 3 Options 4 Back	F≹	
Click on I Wedge or press wedges in standard modes featur		e of linear array probes mounted onto	
		e of linear array probes mounted onto standard modes featuring each instrume	ənt
		e of various PA probes (linear and mate with optional modes, which may vary fr	
Click on Back or press	F4 or Esc to return to PA mod	odality start menu	

5.3. Wedged Linear Array Probes – Standard Modes of Operation

5.3.1. Wedged Linear Array Probes Database

It is necessary to define new wedged linear array probe or select an existing one in the instrument's

Next database for further operation. To proceed click on . On completion click on or press Shift + Enter



To return to the Modes of Operation Menu for PA modality click on

Back or press **Esc**

To enter new probe into the database of modifying data about existing

Add/Edit mode click on This operation is password protected - for the first time new password to be entered by the supervisor so the contents of the database will not be affected unexpectedly in the future

For keying in password it may be used either top panel or virtual keyboard generated on the instrument's screen

Type Old P

Type olu Fasswolu.
Type New Password:
P
Retype New Password:
1 2 3 4 5 6 7 8 9 0 - = \
q w e r t y u ı o p []
asdfghjkl;'
Shift z x c v b n m , . /
Dei BS
OK Cancel



There are 2 groups of parameters to be defined for each probe / wedge, namely Wedge Geometry

and **Element Loc**ation, to select a group for keying in / modifying click on it's name



For most of the parameters their meaning is obviously clear from the sketch indicated on the instrument's screen; among them there are just two parameters requiring more explanation:

- \Box α is designation of **Angle** (Wedge Angle)
- □ **U** is part of the wedge that may not be used for forming ultrasonic field in the material, for example protective metallic shield on the front surface of the wedge

To modify / key in parameter value refer to paragraph 5.3.2 of this Operating Manual

Other controls:

- Export
 export probes database from instrument into a file
- Import import of probes database into instrument from a file
- Change Password
 managing passwords for authorized access to database entries



[—] confirming modified data for the probe existing in the database (probe name to be confirmed)

or press Esc

To return to previous Probe and Wedge Definition screen click on

Typical linear array probes and corresponding wedges are listed below

#	Item	Order Code (Part ##)	Note
1	PA-2M8E1P - LINEAR ARRAY Frequency: 2 MHz Pitch Size: 1 mm Number of Elements: 8 Elevation: 9 mm	S 4922104376	Mark on the probe 104376
2	PA-4M16E0.5P - LINEAR ARRAY Frequency: 4 MHz Pitch Size: 0.5 mm Number of Elements: 16 Elevation: 9 mm	S 4922104377	Mark on the probe 104377
3	VKPA-8/16 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922104376 and S 4922104377 probes	S 4922104378	Suitable for flat surfaces and curved surfaces with OD ≥ 1000 mm Linear array probes equipped with that wedge are defined in the instrument database as □ 104378W36 □ 104377W36
4	VKPA-8/16 CU XXX - 36° wedge (55° central angle for shear wave in low carbon steel) - axially contoured for XXX mm OD /// for S 4922104376 and S 4922104377 probes	S 4922104378 CU XXX	Suitable for OD < 1000 mm Linear array probes equipped with that wedge are defined in the instrument database as I 104378W36CUxxx I 104377W36 CUxxx whereas xxx is OD expressed in mm
5	PA-5M32E0.5P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 0.5 mm Number of Elements: 32 Width (Elevation): 10 mm	S 4922104379	Mark on the probe 104379
6	PA-5M16E1P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 1 mm Number of Elements: 16 Elevation: 10 mm	S4922105503	Mark on the probe 105503
7	PA-7.5M32E0.5P - LINEAR ARRAY Frequency: 7.5 MHz Pitch Size: 0.5 mm Number of Elements: 32 Elevation: 10 mm	S 4944109464	Mark on the probe 109464
8	VKPA-32 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922104379, S4922105503, and S 4944109464 probes	S 4922104380	Suitable for flat surfaces and curved surfaces with OD ≥ 1000 mm Linear array probes equipped with that wedge are defined in the instrument database as □ 104379W36 □ 105503W36 □ 109464W36
9	VKPA-32 CU XXX - 36° wedge (55° central angle for shear wave in low carbon steel) – axially contoured for XXX mm OD /// for S 4922104379, S4922105503, and S 4944109464 probes	S 4922104380 CU XXX	Suitable for OD < 1000 mm Linear array probes equipped with that wedge are defined in the instrument database as 104379W36CUxxx 105503W36CUxxx 109464W36CUxxx whereas xxx is OD expressed in mm

#	Item	Order Code (Part ##)	Note
	PA-5M64E1P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 1 mm Number of Elements: 64 Width: 10 mm	S 4922104381	Mark on the probe 104381
	VKPA-64 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922104381 probe	S 4922705119	Suitable for flat surfaces and curved surfaces with OD ≥ 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 104381W36
	VKPA-64 CU XXX - 36° wedge - 36° wedge (55° central angle for shear wave in low carbon steel) – axially contoured for XXXX mm OD /// for S 4922104381 probe	S 4922705119 CU XXXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as 104381W36CUxxx whereas xxx is OD expressed in mm
	PA-2.25M16E1P - LINEAR ARRAY Frequency: 2.25 MHz Pitch Size: 1 mm Number of Elements: 16 Elevation: 13 mm	S 4922105504	Mark on the probe 105504
	VKPA-16/1 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922105504 probe	S 4922104679	Suitable for flat surfaces and curved surfaces with OD ≥ 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 105504W36
	VKPA-16/1 CU XXX - 36° wedge (55° central angle for shear wave in low carbon steel) – axially contoured for XXX mm OD /// for S 4922105504 probe	S 4922104679 CU XXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as 105504W36CUxxx whereas xxx is OD expressed in mm
16	PA-2.25M16E1.5P - LINEAR ARRAY Frequency: 2.25 MHz Pitch Size: 1.5 mm Number of Elements: 16 Elevation: 19 mm	S 4922105505	Mark on the probe 105505
	VKPA-16/1.5 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922105505 probe	S 4922104680	Suitable for flat surfaces and curved surfaces with OD ≥ 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 105505W36
	VKPA-16/1.5 CU XXX - 36° wedge (55° central angle for shear wave in low carbon steel) – axially contoured for XXX mm OD /// for S 4922105505 probe	S 4922104680 CU XXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as 105505W36CUxxx whereas xxx is OD expressed in mm

#	Item	Order Code (Part ##)	Note
	PA-1.5M16E1P - LINEAR ARRAY Frequency: 1.5 MHz Pitch Size: 1 mm Number of Elements: 16 Elevation: 12 mm	S 4922107553	Mark on the probe 107553
20	VPKA-38-16-1-21 - 38° wedge (59° central angle for shear wave in low carbon steel) for S 4922107553 probe	S 4944262021	Suitable for flat surfaces and curved surfaces with OD ≥ 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 107553W39-21
21	VPKA-38-16-1-12 - 38° wedge (59° central angle for shear wave in low carbon steel) for S 4922107553 probe	S 4944262012	Suitable for flat surfaces and curved surfaces with OD ≥ 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 107553W39-12
22	VPKA-38-16-1-21 CU XXX - 38° wedge (59° central angle for shear wave in low carbon steel) – axially contoured for XXX mm OD /// for S 4922107553 probe	S 4944262021 CU XXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as I 107553W39-21CUxxx whereas xxx is OD expressed in mm
23	VPKA-38-16-1-12 CU XXX - 38° wedge (59° central angle for shear wave in low carbon steel) – axially contoured for XXX mm OD /// for S 4922107553 probe	S 4944262012 CU XXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 107553W39-12CUxxx whereas xxx is OD expressed in mm



5.3.2. General Rule for Keying In / Modifying Parameter

5.3.3. ISONIC PA Pulser Receiver – Wedged Linear Array Probes

5.3.3.1. Operating Surface

ISONIC 2009 UPA Scope comprises 64 identical pulser receiver channels, which may be used in any combination to form ultrasonic beams in the material and receive echoes with use of PA probes. Manual control is implemented through main operating SW, which is similar to the operating surface of Sonontron NDT's flaw detectors working with conventional and TOFD probes



The **Main Menu** consists of ten topics; each topic is associated with corresponding **submenu** appearing as vertical bar showing names for five parameters or modes of operation, their current settings and current value of increment/decrement for a parameter. The active topic is highlighted. To select a topic click on its

name or on 🔄 or press 与

To modify parameter or mode within the active topic proceed according to paragraph 5.3.2 of this Operating Manual

5.3.3.2. Sub Menu BASICS



All settings controllable through **BASICS** sub menu are typical for conventional ultrasonic flaw detector and have the same meaning for the PA modality. To modify the desired setting proceed according to paragraph 5.3.2 of this Operating Manual. Also please refer to the below notes

1

٠

٠

Gain and Range

Modifying of **Gain** and **Range** settings is also possible through a number of other submenus

US Velocity

Like in regular ultrasonic flaw detectors (conventional modality) proper **US Velocity** setting is important for correct:

- A-Scan time base setting
- Automatic measurements of reflector coordinates

Whilst implementing PA modality proper **US Velocity** setting is additionally important for correct forming of focal laws for the emitting and receiving signals. Hence **US Velocity** to be keyed in precisely for the desired type of wave to be generated in the material and for the expectedly received signals

Display Delay

Display Delay may be controlled manually as in the regular ultrasonic flaw detector. However **Probe Delay** of PA probe is depending on plenty of factors such as emitting and receiving aperture and focal law to be implemented – refer to paragraphs 5.3.3.9, 5.3.3.10, and 5.3.3.11 of this Operating Manual. And for practical use very often it is important to equalize **Display Delay** and **Probe Delay** so start point of the A-Scan will correspond to the material surface. To activate / deactivate automatic performing of such equalizing (**Surface**

Align) click on



then click on \checkmark or press \uparrow , \rightarrow , \leftarrow , \downarrow then click on \circ or press **Enter** or **Esc**. Automatic **Surface Align** will be deactivated automatically upon performing manual modifying of **Display Delay**

<u>Reject</u>

- Signals below Reject level (small signals) are suppressed
- Signals exceeding Reject level (large signals) are presented on the A-Scan without affecting their original height
- Part of large signal wave form below Reject level is suppressed



- Reject level may be applied to rectified signals only (Display Modes Full, NegHalf and PosHalf refer to paragraph 5.3.3.4 of this Operating Manual)
- Reject setup is also possible through a number of other submenus following the same rules as above

5.3.3.3. Sub Menu PULSER



All settings controllable through **PULSER** sub menu are typical for conventional ultrasonic flaw detector and have the same meaning for the PA modality. To modify the desired setting proceed according to paragraph 5.3.2 of this Operating Manual. Also please refer to the below notes

()

Pulser Modes

There are two Pulser Modes available:

- SINGLE for that mode emitting and receiving aperture within entire PA probe are fully matching; focal point, incidence angle, and type of wave for the receiving and emitting aperture are identical and controlled synchronously
- DUAL for that mode emitting and receiving aperture within entire PA probe may be either fully matching or fully mismatching or partially matching; focal point, incidence angle, and type of wave are controlled separately

Refer to paragraphs 5.3.3.4 of this Operating Manual

Pulse Width

- **Pulse Width** (Duration of Half Wave of Bipolar Square Wave Initial Pulse) is tunable between 50 ns to 600 ns in 5 ns steps
- Durations of positive and negative half wave of the initial pulse are varying synchronously
- Attempt to decrease Pulse Width below 50 ns switches initial pulse OFF and channel may be used then as receiver only

Firing Level

There are 12 grades (1 through 12) for setting **Firing Level** – amplitude of initial pulse is controlled from 100 V peak to peak (**Firing Level = 1**) to 300 V peak to peak (**Firing Level = 12**)

<u>PRF</u>

PRF is indicated for single pulsing / receiving cycle (single focal law)

5.3.3.4. Sub Menus EMIT and RECEIVE

5.3.3.4.1. Definitions

Emitting Aperture - quantity of elements of linear array probe involved into emitting of ultrasonic wave

Receiving Aperture - quantity of elements of linear array probe involved into receiving of ultrasonic signals

Start - number of the first element of the emitting / receiving aperture

Focal Distance - material travel distance between incidence point and focal point

Focal Depth - depth of the focal point measured relatively contact surface of the material

Ultrasonic wave in the material is formed through superimposing of waves generated by all elements of the emitting aperture. The incidence angle and focal distance (depth) for the emitted ultrasonic wave are controlled electronically through phasing of initial pulses generated by the instrument on the elements of emitting aperture

Every element of the receiving aperture receives ultrasonic pulses from the material independently on others and converts them into electrical signals. Electrical signals from all elements of the receiving aperture are gained and digitized independently on each other then superimposed mathematically with use of digital phasing providing control of incidence angle and focal distance (depth) for the superimposed signal

5.3.3.4.2. Pulser Mode = SINGLE – Full Matching of Emitting and Receiving Aperture

For **Pulser Mode = SINGLE** emitting and receiving aperture within entire PA probe are fully matching; focal point, incidence angle, and type of wave for the receiving and emitting aperture are identical and controlled synchronously



5.3.3.4.3. Pulser Mode = DUAL – Partial Matching of Emitting and Receiving Aperture

For **Pulser Mode = DUAL** emitting and receiving aperture within entire PA probe may be:

- fully matching
- fully mismatching
- partially matching

For all above the focal point, incidence angle, and type of wave are controlled separately separately from each other for the emitting and receiving aperture



5.3.3.4.4. Material Thickness

The are two modes of pulsing / receiving – with (**Thickness Correction = ON**) and without (**Thickness Correction = OFF**) considering thickness of the material

Thickness Correction = OFF	Thickness Correction = ON
Parameter of focusing is Focal Distance : For the given Focal Distance varying of incidence angle will cause varying of Focal Depth – refer to paragraph 5.3.3.4.1 of this Operating Manual	Parameter of focusing is Focal Depth : For the given Focal Depth varying of incidence angle will cause varying of Focal Distance – refer to paragraph 5.3.3.4.1 of this Operating Manual; i.e. focusing is performed along horizontal line parallel to the contact surface of the material
Imaging of the ultrasonic beam is implemented as for semi-finite space, the reflections from the walls are ignored	Imaging of the ultrasonic beam is implemented through considering of Skips , Incidence Angle , and material Thickness

Thickness Correction = OFF

Parameters **Thickness**, **Emitter Skip**, **Receiver Skip** ignored Focusing is defined through keying in **Focal Distance**



Thickness Correction = ON Parameters Thickness, Emitter Skip, Receiver Skip are considered Focusing is defined through keying in Focal Distance



To modify the desired setting (**Thickness Correction**, **Thickness**, **Emitter Skip**, **Receiver Skip**) proceed according to paragraph 5.3.2 of this Operating Manual. Also please refer to the below notes

5.3.3.5. Sub Menu RECEIVER



All settings controllable through **RECEIVER** sub menu are typical for conventional ultrasonic flaw detector and have the same meaning for the PA modality. To modify the desired setting proceed according to paragraph 5.3.2 of this Operating Manual. Also please refer to the below notes

Display Mode

There are four **Display modes** for time domain signal presentation:



5.3.3.6. Sub Menus GATE A and GATE B

1 Gain 22 dB	< i 🕨	1 Gain 22 dB	4 🕯 🕨
a Switch ON	4 🖻 🕨	b Switch OFF	🖄 🗭
2 a Start 2 mm	4 3 🕨	2 b Start 50 mm	4 3 🕨
2 aWidth 6 mm	4 4	2 bWidth 20 mm	• 4 •
10 aThreshol 20%	d 🏟 💰 🗭	10 bThreshold 40%	🔶 🗴 🗭

All settings controllable through **GATE A** and **GATE A** sub menus are typical for conventional ultrasonic flaw detector and have the same meaning for the PA modality. To modify the desired setting proceed according to paragraph 5.3.2 of this Operating Manual. Also please refer to the below notes

1

- **aStart** setup is also possible through a number of other submenus following the same rules as above
- Counting of aStart value starts after completing count of Probe Delay refer to paragraphs 5.2.12 and 5.2.13 of this Operating Manual
- Counting of bStart value starts after finishing of Probe Delay count (refer to paragraph 5.2.12 and 5.2.13 of this Operating Manual)
- Gates A and B may be manipulated through Drag and Drop provided that they are visible in the A-Scan area. Mouse pointer changes shape upon placing it above appropriate part of the gate



To control gate press and hold left mouse button or touch screen with stylus the and drag and drop through releasing of left mouse button or touch screen stylus

5.3.3.7. Sub Menu ALARM



All settings controllable through **ALARM** sub menu are typical for conventional ultrasonic flaw detector and have the same meaning for the PA modality. To modify the desired setting proceed according to paragraph 5.3.2 of this Operating Manual. Also please refer to the below notes



- There is a pulse matching with Gate A and exceeding its threshold; the Alarm Logic setting for Gate A is Positive
 Alarm Indicator for Gate A is active
- There is a pulse matching with Gate B and not exceeding its threshold; the Alarm Logic setting for Gate B is Negative
 Alarm Indicator for the Gate B is active

5.3.3.8. Sub Menu DAC/TCG



All settings controllable through **DAC/TCG** sub menu are typical for conventional ultrasonic flaw detector and have the same meaning for the PA modality. To modify the desired setting proceed according to paragraph 5.3.2 of this Operating Manual. Also please refer to the below notes

1

- There are four possible modes for DAC/TCG:
 - There are four possible modes for **DAC/TCG**:
 - OFF DAC Curve switches automatically to OFF while in OFF
 - DAC available if quantity of stored echoes is 2 (two) or more. DAC Curve switches automatically to ON while in DAC mode. Both experimental and theoretical methods for creating DAC are available
 - TCG available if quantity of stored echoes is 2 (two) or more. DAC Curve switches automatically to OFF while in TCG mode
 - Update allows to create/update new/existing DAC. Update of existing DAC performed through erasing of a number of sequentially recorded echoes, starting from the latest one, and/or recording of new echoes. The maximal number of echoes recorded into the one DAC is 40 (forty). DAC Curve switches automatically to ON if the number of recorded echoes is 2 (two) or more and switches automatically to OFF if number of recorded echoes is less than 2 (two) while in Update mode
- It is possible to Create / Modify / Activate DAC and TCG for all Display modes (RF, Full, Negative, and Positive)
- To create / modify **DAC/TCG** refer to paragraph 5.3.3.8 of this Operating Manual

5.3.3.9. Create / Modify DAC

5.3.3.9.1 Theoretical DAC: dB/mm (dB/in)

Theoretical **DAC** represents exponential law for distance amplitude curve determined by **dB/mm** (**dB/in**) factor applied to pure material travel distance. The start point of **DAC** is contact surface and at that point DAC starts at 100% of A-Scan height. Theoretical **DAC** count starts immediately upon completion of **Probe Delay** count – refer to paragraphs 5.3.3.9 of this Operating Manual



Set DAC/TCG/DGS to Update then click on



5.3.3.9.2 Experimental DAC: Recording Signals From Variously Located Reflectors

Prior to building experimental **DAC** switch theoretical **DAC** off and **Gate A** on. Set **DAC/TCG** to **Update**. Place probe onto **DAC** calibration block and maximize echo from the reflector closest to the probe (first echo) then place **Gate A** over received signal and capture first *DAC echo* through click on or press or \uparrow , \rightarrow



1

As a result the *first DAC echo* will be stored accompanied with corresponding indication:

Place probe onto DAC calibration block and maximize echo from next reflector then place **Gate A** over received signal and capture *next DAC echo*. As result next *DAC echo* will be stored causing appropriate modifying of corresponding indications



\bigcirc

- The highest echo in the Gate A will be stored said echo may either exceed Gate A threshold level or not
- Stored echo must be below 100% of A-Scan height
- A total number of 40 echoes may be stored one by one by the same way as described above
- After creating a DAC (2 or more echoes stored) the DAC and / or TCG may be activated
- There are two styles of DAC indication in the DAC mode: Main Curve Only and Main Curve ± N dB,
 DAC Curve
- where N may be setup between ±1 and ±14 dB with 1 dB increment: Curve±3dB
 It's possible to erase the last stored echo from the DAC. To proceed set the DAC/TCG to Update and

3

switch on **Gate A** then click on click on \mathbf{N} or press \leftarrow, \Downarrow :

5.3.3.10. Sub Menu MEASURE



All settings controllable through **MEASURE** sub menu are typical for conventional ultrasonic flaw detector and have the same meaning for the PA modality. To modify the desired setting proceed according to paragraph 5.3.2 of this Operating Manual. Also please refer to the below notes

- Refer to paragraph 5.3.3.11 of this Operating Manual for information about values available for automatic measurement and indication in the Value Box (Digital Readout)
- There are four Measurement Modes possible:
 - Flank
 - ♦ Top
 - ♦ Flank-First
 - Top-First
- Probe Delay is determined by instrument automatically for all possible combinations of the following parameters:

Pulser Mode = SINGLE	Pulser Mode = DUAL
Aperture Start Incidence Angle Focal Distance (for Thickness Correction = ON) or Focal Depth (for Thickness Correction = OFF) USVelocity Wedge Velocity	EMIT Aperture EMIT Start EMIT Incidence Angle RECEIVE Aperture RECEIVE Start RECEIVE Incidence Angle Focal Distance (for Thickness Correction = ON) or Focal Depth (for Thickness Correction = OFF) USVelocity Wedge Velocity

5.3.3.11. A-Scan Based Measurements

5.3.3.11.1. Measured Values





Value 1: T(A) / Value 2: T(B)

Time of Flight - μs of an echo matching with Gate A / Gate B measured respectfully Incidence Point:

> T(A) = Absolute Delay A - Probe Delay T(B) = Absolute Delay B - Probe Delay

Value 3: **s(A)** / Value 4: **s(B)**

Material Travel Distance - mm or in of an echo matching with Gate A / Gate B measured respectfully *Incidence Point*:

 $s(A) = \frac{1}{2} \cdot T(A) \cdot US$ Velocity $s(B) = \frac{1}{2} \cdot T(B) \cdot US$ Velocity

Value 5: a(A) / Value 6: a(B)

Projection Distance - mm or **in** of reflector returning an echo matching with **Gate A** / **Gate B**, measured respectfully front surface of the PA probe with taking into account migration of *Incident Point* and varying X-*Value* in accordance with varying *Incidence Angle* α:

> $a(A) = s(A) \cdot sin (\alpha) - X$ -value $a(B) = s(B) \cdot sin (\alpha) - X$ -value

Value 7: t(A) / Value 8: t(B)

Depth - **mm** or **in** of reflector returning an echo matching with **Gate A** / **Gate B**:

 $t(A) = s(A) \cdot \cos (\alpha)$ $t(B) = s(B) \cdot \cos (\alpha)$

Value 9: ∆T - µs:

Value 11: ∆a - mm or in:

Value 12: Δt - mm or in:

∆s = s(B) – s(A) ∆a = a(B) – a(A) ∆t = t(B) – t(A)

 $\Delta T = T(B) - T(A)$



Value 13: H(A) / Value 14: H(B)

Amplitude - % of A-Scan height of an echo matching with Gate A / Gate B

Value 15: V(A) / Value 16: V(B)

Amplitude - dB of an echo matching with Gate A / Gate B with respect to aThreshold:

 $V(A) = 20 \cdot \log_{10} (H(A) / aThreshold)$ $V(B) = 20 \cdot \log_{10} (H(B) / bThreshold)$

Value 17: ∆V - dB:

 $\Delta V = V(B) - V(A)$

Value 18: $\Delta VC(A)$ (dB to DAC) – dB:

 $\Delta VC(A) = 20 \cdot \log_{10} (H(A) / C (Absolute Delay A_Top))$

Value 19: $\Delta VC(B)$ (dB to DAC) – dB:

 $\Delta VC(B) = 20 \cdot \log_{10} (H(B) / C (Absolute Delay B_Top))$

1

- To proceed the corresponding Gate or both Gates to be active
- ΔVC(A) (dB to DAC) measurements require active DAC
- Amplitude measurements of echoes may be performed provided their heights don't exceed 130% of A-Scan height
- For 2 and more echoes matching with the Gate refer to paragraph 5.3. 3.11.2 of this Operating Manual

5.3.3.11.2. Measuring Modes

The table below represents distinguishing points on an **A-Scan**, which will be taken for automatic measurements depending on **Meas Mode** setting



5.3.3.11.3. Thickness Correction

The sketch below represents positioning of PA Probe on the plate and on the tube wall (longitudinal insonification).



With reference to paragraph 5.3.3.4.4 of this Operating Manual on case of

Thickness Correction = ON

for half skip, full skip, and multi skip insonification **t(A)**, **t(B)** readings will represent actual depth of the targeted reflector provided the **Thickness** is entered properly

5.3.3.12. Freeze A-Scan

1

To freeze / freeze peak / unfreeze the **A-Scan** click on or press

• Freeze Peak mode allows representing of Hilbert envelop for sequence of echoes obtained while manipulating probe over some reflector. This function may be useful for localization of echo maximum whilst in the A-Scan mode:

or F10 or <Alt>+<F>



• Freeze Peak mode may not be activated for RF signal presentation



at the upper left corner of **A-Scan** indicates that it is frozen (**Freeze**)



Appearing of *Mathematical States and Content of A-Scan* indicates that **Freeze Peak** mode is active

- The following operations are available for the frozen **A-Scan**:
 - Varying Gain in ± 6 dB range
 - o Manipulating Gates A and B
 - o Varying Alarm mode
 - Selecting parameter (**Meas Value**) for automatic measurements and obtaining corresponding digital readout
- Caption of appropriate button changes window upon freeze / freeze peak / unfreeze A-Scan:



5.3.3.13. Save A-Scan and Calibration Data Into a File



5.3.3.14. Load A-Scan and Calibration Data From a File

Click on or press F12

5.3.3.15. Print A-Scan Settings List

Click on Print

5.3.3.16. Preview Current PA Probe in Use

Click on 🕒

5.3.3.17. Direction of Graphical Presentation



5.3.3.18. Activate Main Recording Menu

Click on **I** or press **Shift** + **Enter**

5.3.3.19. Return to Linear Array Probes Database

Click on Close or press Esc

5.3.4. Main Recording Menu

	1 ABI Scan		
	2 Sector Scan		
	3 Tandem Scan	R.	
	4 Back	-0	
Click on I ABI Scan or press based inspections	s F1 to proceed with ABI Scan	(other know	n names – B-Scan and E-Scan)
Click on Sector Scan or press	s F2 to proceed with Sector Sc	an (S-Scan)	based inspections
Click on Tandem Scan or press elements PA probe is necessary	s F3 to proceed with unique Ta)	indem B-Sca	n based inspections (64
Click on Back or press	s F4 or Esc to return to ISON	C PA Pulse	r Reciver

5.3.4.1. ABI Scan (B-Scan, E-Scan)

B-Scan (E-Scan) image is obtained through insonification of the material at fixed incidence angle through electronic shift of predetermined aperture within entire linear array comprising more elements than aperture size. Movie illustrating electronic scanning required for creation of **B-Scan** is available for viewing / download at http://www.sonotronndt.com/PDF/OM2009/BScan_Wedge.wmv

5.3.4.1.1. Settings of PA Pulser Receiver

With reference to paragraph 5.3.3 of this Operating Manual the following settings to be provided

#	Parameter or Mode	Required Settings	Note
1	Pulser Mode	SINGLE	
2	Aperture	4 ≤ Aperture ≤ N/2 whereas N is total <i>Number Of</i> <i>Elements</i> in the linear array probe	
3	Incidence Angle	According to inspection procedure	
5	Thickness Correction	ON	
5	Thickness	Equal to the actual value of material thickness	
6	Emitter / Receiver Skip	In accordance with the inspection procedure	
7	Focal Depth	In accordance with the inspection procedure	
8	USVelocity	Equal to the actual value of ultrasound velocity in the object under test either for shear or longitudinal waves	
9	Start	1	Only at the stage of setting Gain
10	Gain	Gain setting to be performed according to inspection procedure providing required echo heights from defects to be detected	
11	DAC/TCG	DAC/TCG settings to meet requirements of inspection procedure	
12	Pulse Width, Firing Level	Pulse Width and Firing Level settings to optimize signal to noise ratio Pulse Width to be around 1/F where F is frequency of PA probe	To synchronize with Gain setting – finalize setting of Pulse Width and Firing Level before setting of the Gain
13	Filter, Low Cut, and High Cut Frequencies	Filter and Low Cut and High Cut settings to match with frequency of PA probe to optimize signal to noise ratio	To synchronize with Gain setting – finalize setting of Filter, Low Cut, and High Cut before setting of the Gain
14	Display	Display setting may be either Full , RF , PosHalf , or NegHalf – follow requirements the inspection procedure	
15	Surface Alignment	ON	
16	Range	To provide representation of all reflectors used for Gain and DAC calibration	Only at the stage of setting Gain and DAC

On completing calibration of ISONIC PA Pulser Receiver:

- Place PA probe into position providing receiving of maximized echo from reference reflector, for example

 side drilled hole (SDH), then hold it in the found position
- Perform Range setting providing appearance of the said echo at 50% of the A-Scan width
- Remember existing Gain setting as G0 then bring the amplitude of reference reflector to standard level (~80% of A-Scan height)
- Click on I or press Shift + Enter to proceed with Gain Per Shot Correction


5.3.4.1.2. Gain Per Shot Correction

The following effects to be compensated to equalize the sensitivity over entire B-Scan insonification with wedged linear array probes:

- Inequality of elements of PA probe (parameters elements PA probe may deviate in certain range)
- Wedge sound path / losses are different for each implemented pulsing receiving shot (focal law)

This is a unique feature of **ISONIC 2009 UPA Scope** that each focal law may be implemented with individually adjusted gain – the screen below allows performing *Gain Per Shot* (*Gain Per Focal Law*) correction:



On completion:

- Click on Back or press Esc to return to ISONIC PA Pulser Receiver then return Gain setting to G0 as per paragraph 5.3.4.1.1 of This Operating Manual
- Click on I or press Shift + Enter this will return Gain Per Shot Correction screen
- Click on vert or press **Shift** + **Enter** to proceed with **B-Scan**

5.3.4.1.3. B-Scan – ABI Scan Screen



5.3.4.1.4. Color Palette – ABI Scan Screen

On the $\ensuremath{\textbf{B-Scan}}$ image ach color represents corresponding signal amplitude

click on	Coloring
	Pseudo2
then select the needful	Pseudo2 Pseudo Pseudo2 Grayscale Thermal
Customize palette through appropriate dialogue control:	Custom.
Custom Color 42.0 41.5 40.7 39.8 37.8 36.3 34.8 32.9 30.4 27.0 21.4 0.0 Interval Origin Start 10 Number Of Colors 10 <td></td>	
Cancel	

There are 4 customizable color palettes available, to select / customize

5.3.4.1.5. 3D Data Recording Through Linear Scanning (C-Scan, Top and Side Views)

3D data recording is provided through linear scanning according to the sketch below

Close

Start





5.3.4.2. Sector Scan (S-Scan)

S-Scan image is obtained through insonification of the material through varying of incidence angle in a certain range whilst the aperture is fixed. Movie illustrating electronic scanning required for creation of **S-Scan** is available for viewing / download at

http://www.sonotronndt.com/PDF/OM2009/S_Scan_Wedge.wmv

5.3.4.2.1. Settings of PA Pulser Receiver

With reference to paragraph 5.3.3 of this Operating Manual the following settings to be provided

#	Parameter or Mode	Required Settings	Note
1	Pulser Mode	SINGLE	
2	Aperture	$4 \leq Aperture \leq N$ whereas N is total <i>Number Of Elements</i> in the linear array probe	
3	Incidence Angle	A value within required varying range for incidence angle in accordance with the inspection procedure	Only at the stage of setting Gain
5	Thickness Correction	OFF – regular S-Scan ON – TTGI S-Scan (TTGI – unique <i>True To Geometry</i> <i>Imaging</i> technology from Sonotron NDT)	
5	Thickness	Equal to the actual value of material thickness	For TTGI S-Scan only
6	Emitter / Receiver Skip	In accordance with the inspection procedure	For TTGI S-Scan only
7	Focal Depth	In accordance with the inspection procedure	For TTGI S-Scan only
8	Focal Distance	In accordance with the inspection procedure	For regular S-Scan only
9	USVelocity	Equal to the actual value of ultrasound velocity in the object under test either for shear or longitudinal waves	
9	Start	According to inspection procedure Start ≤ N – Aperture whereas N is total <i>Number Of</i> <i>Elements</i> in the linear array probe	Only at the stage of setting Gain
10	Gain	Gain setting to be performed according to inspection procedure providing required echo heights from defects to be detected	
11	DAC/TCG	DAC/TCG settings to meet requirements of inspection procedure	
12	Pulse Width, Firing Level	Firing Pulse Width and Firing Level settings to optimize signal to noise ratio Pulse Width to be around 1/F where F is frequency of PA probe	
13	Filter, Low Cut, and High Cut Frequencies		
14	Display	Display setting may be either Full, RF, PosHalf, or NegHalf – follow requirements the inspection procedure	
15	Surface Alignment	ON	
16	Range	For Thickness Correction = OFF (regular S-Scan) Range to cover whole area according to the inspection procedure	
		For Thickness Correction = ON (TTGI S-Scan) Range setting is important at the stage of Gain and DAC setup only providing representation of all reflectors used for Gain and DAC calibration	

On completing calibration of ISONIC PA Pulser Receiver:

- Keep Incidence Angle setting to remain the same is it was used for calibration of Gain, remember this setting as α_n
- If the intend is performing of regular **S-Scan** remember existing **Range** setting as **R0**; for **TTGI S-Scan** simply ignore this note
- Set Range value to 200 mm (or 8 in)
- Remember USVelocity settings as USVel0
- If the intend is performing of shear wave inspection the set USVelocity to 3250 m/s (128.1 in/ms); if intend is performing of compression (longitudinal) wave inspection then set USVelocity to 5920 m/s (or 231.1 in/ms)
- Remember existing **Gain** setting as **G0**

- Place PA probe into position providing receiving of maximized echo from 100 mm radius reflector in the V1 calibration block, bring maximized echo to the standard level (~80% of A-Scan height) then hold probe it in the found position
- Click on or press **Shift** + **Enter** to proceed with *Gain Per Shot Correction*



5.3.4.2.2. Angle Gain Compensation

The following effects to be compensated to equalize the sensitivity over entire B-Scan insonification with wedged linear array probes:

 Among other factors echo amplitude is determined by energy of refracted wave, which strongly depends on incidence angle as transparency of probe-material interface varies along with varying of incidence angle

EchoAmplitude ~ *Energy*







- α₀ > α_{cr1} γ_{L1} Migr α₀ α₁ γ_{S2} γ_{S2} γ_{S2}

 $EffectiveSize = N \times PitchSize \times Cos(\Delta \alpha)$

Among other factors echo amplitude depends on effective size of the aperture, which varies along with varying of incidence angle

EchoAmplitude ~ *EffectiveSize*²

 Wedge sound path / losses are different for each implemented pulsing receiving shot (focal law) due to migration of incidence point

EchoAmplitude ~ $Exp(-V_{L1} \times probe_delay)$

This is a unique feature of **ISONIC 2009 UPA Scope** that each focal law may be implemented with individually adjusted gain – the screen below allows performing *Gain Per Angle* (*Gain Per Focal Law*) correction as well as keying in *range of varying incidence angle within entire S-Scan cycle* and *increment of varying incidence angle*:



- return **Gain** setting to **G0** as per paragraph 5.3.4.2.1 of This Operating Manual
- o return USVelocity to USVelo as per paragraph 5.3.4.2.1 of This Operating Manual
- return Range setting as R0 as per paragraph 5.3.4.2.1 of This Operating Manual for regular S-Scan; for TTGI S-Scan simply ignore this note
- Click on **I** or press **Shift** + **Enter** this will return *Gain Per Angle Correction* screen
- Click on _____ or press Shift + Enter to proceed with B-Scan

5.3.4.2.3. S-Scan – Sector Scan Screen

regular S-Scan



5.3.4.2.4. Color Palette – Sector Scan Screen

Refer to paragraph 5.3.4.1.4 of this Operating Manual

5.3.4.2.5. 3D Data Recording Through Linear Scanning (C-Scan, Top and Side Views)

Refer to paragraph 5.3.4.1.5 of this Operating Manual

5.3.4.3. Tandem B-Scan

Tandem B-Scan is unique technology implemented by **ISONIC 2009 UPA Scope** instrument for the detection of vertically oriented planar defects, for example – fatigue cracks. It is executed with use of 64 elements linear array probes through **Dual** mode of pulsing receiving. Sequence of the realized pulsing receiving shots provides sequential passing by focal point through centers of cells composing insonified region of interest (ROI) in the material. Emitting and receiving aperture and ultrasonic beam trace are varying for each implemented focal law. Movie illustrating electronic scanning required for creating of **Tandem B-Scan** is available for viewing / download at

http://www.sonotronndt.com/PDF/OM2009/Tandem_B_Scan.wmv

5.3.4.3.1. Preliminary Settings of PA Pulser Receiver

With reference to paragraph 5.3.3 of this Operating Manual the following preliminary settings to be provided

#	Parameter or Mode	Required Settings	Note
1	Pulser Mode	DUAL	
2	Thickness Correction	ON	
3	Thickness	Equal to the actual value of material thickness	
4	USVelocity	Equal to the actual value of shear wave velocity in the object under test	
5	DAC/TCG	OFF	
6	Pulse Width, Firing Level	Pulse Width and Firing Level settings to optimize signal to noise ratio Pulse Width to be around 1/F where F is frequency of PA probe	To synchronize with Gain setting
7	Filter, Low Cut, and High Cut Frequencies	Filter and Low Cut and High Cut settings to match with frequency of PA probe to optimize signal to noise ratio	To synchronize with Gain setting – finalize setting of Filter, Low Cut, and High Cut before setting of the Gain
8	Display	Display setting may be either Full , RF , PosHalf , or NegHalf – follow requirements the inspection procedure	
9	Surface Alignment	ON	
10	Gain	5060 dB	Recommended value to start with

5.3.4.3.2. Region of Interest

On completing with preliminary settings of **ISONIC PA Pulser Receiver** click on

or press **Shift** + **Enter** to proceed with defining of ROI (*Region Of Interest*) through specially dedicated screen. After defining **ROI Width**, **Probe To ROI**

Distance, and Grid Size click on Next

or press **Shift** + **Enter** to enter to *Gain Per Shot Correction* screen



A = Probe To ROI Distance B = ROI Width C = Grid Size

5.3.4.3.3. Calibration Block For Tandem B-Scan Technology

Calibration block for the implementation of **Tandem B-Scan** technology to be manufactured from the same material as object under test. It must contain reference reflector either FBH (flat bottom hole) or SDH (side drilled hole) situated according to the sketch and free vertical wall. Diameter of FBH / SDH to be defined according to the requirements to inspection sensitivity. Length of calibration block to allow performing of all manipulations described in the present chapter



5.3.4.3.4. Automatic Ray Tracing

Upon entering Gain Per Shot Correction screen ISONIC 2009 UPA Scope instrument performs automatic ray tracing providing insonifying grids within entire ROI. At that stage PA probe to remain uncoupled to the calibration block. As a result a number of grids composing ROI will be painted while some grids will remain unpainted (white). Unpainted grids indicate areas within ROI, which may not be insonified for the selected Probe to ROI Distance in the previous screen. It is possible to return back to Region Of Interest screen and to progress to Gain Per Shot Correction screen again several times to maximize number of insonified grids. On reaching the goal click on the grid situated as it is shown on the screenshot whilst PA probe is still not coupled to calibration block - the ray tracing will be shown for the selected grid - the emitted beam (blue) and beam corresponding to the echo from flat or compact reflector provided the reflector would be situated in the designated grid (red). The ray tracing clearly indicates number of skips (EMIT Skip (ESk) and RECEIVE Skip (RSk) settings) implemented by the

emitted and received beam in that case.



Also the numerical indication for the following settings of emitting and receiving aperture appears:

- EMIT Star (ESt)
- EMIT Aperture (EA)
- RECEIVE Start (RS)
- Receive Aperture (RA)
- Incidence Angle (α) the same value for emitting and receiving aperture

Remember required settings the click on Back or press **Esc** to return to *Region Of Interest* screen, in

which click on Back or press Esc to return to ISONIC PA Pulser Receiver screen for Gain calibration

5.3.4.3.5. Setting Gain For Tandem B-Scan Technology

#	Parameter or Mode	Required Settings	Note
1	EMIT Skip	ESk	
2	EMIT Start	ESt	
3	EMIT Aperture	EA	
4	EMIT Angle	α	
5	RECEIVE Skip	RSk	
6	RECEIVE Start	RS	
7	RECEIVE Aperture	RS	
8	RECEIVE Angle	α	
9	Range	$Range = \frac{Thickness \times \left[2 \times \left(EMITSkip + RECEIVESkip\right) - 1\right]}{Cos(\alpha)}$	This Range setting provides appearance of the echo from reference reflector at 50% of A- Scan width

In the ISONIC PA Pulser Receiver screen provide settings as below:



Upon completion pace probe into **Position 1** on the calibration block whereas

D = Probe to ROI Distance + 0.5×Grid Size

and provide **Gain** setting bringing the echo from reference reflector to the standard level, for example 80% of the A-Scan height. Remember obtained Gain value as **G0**



Then place probe into **Position 2**, whereas

D = Probe to ROI Distance + 0.5×Grid Size

and provide **Gain** setting bringing the echo from vertical wall to the standard level

Continue holding of PA probe in the

Position 2 and click on or press **Shift** + **Enter** – this will open *Region Of Interest* screen, from which proceed further to *Gain Per Shot Correction* screen immediately through click on





Position 2

D

Click on the grid situated as it is shown on the screenshot to ensure that the amplitude of echo received from the middle of vertical wall is kept at the standard level



This is a unique feature of ISONIC 2009 UPA Scope that each focal law may be implemented with individually adjusted gain. This allows equalizing of sensitivity within entire ROI whilst implementing Tandem B-Scan insonification. To proceed holding of PA probe in the Position 2 and click on each grid one by one. For every greed A-Scan time base settings (Display Delay and Range) are adjusted automatically by such way that the echo from vertical wall is indicated at the same horizontal position - 50% of A-Scan width so it is necessary just to bring echo amplitude for each grid to the standard level using

Gain Correction **0 dB**

control

At the end of the procedure all grids will have the same color as the greed corresponding to the echo received from the middle of vertical wall

\bigcirc

- Gain Correction for the echo received from the middle of vertical wall to be 0 dB
- Gain Per Shot Correction Matrix may be stored into a file and uploaded at any moment for future use –



On completion:

- Return to ISONIC PA Pulser Receiver then return Gain setting to G0 as per paragraph 5.3.4.3.5 of This Operating Manual
- Return to Gain Per Shot Correction screen and Click





5.3.4.3.7. Tandem B-Scan



5.3.4.3.8. Color Palette – Tandem Scan Screen

Refer to paragraph 5.3.4.1.4 of this Operating Manual

5.3.4.3.9. 3D Data Recording Through Linear Scanning (C-Scan, Top and Side Views)

Refer to paragraph 5.3.4.1.5 of this Operating Manual and screenshot below

5.4. Linear Array Probes With Straight Delay Line – Standard Modes of Operation

Use of linear array probe with straight delay line with **ISONIC 2009 UPA Scope** is based on the same principles and controls as for wedged linear array probes. The following modes of functioning are possible:

- Selecting of PA probe from database, editing existing and adding new PA probe data, exportation and importation of PA probe data base to/from another instrument – refer to paragraph 5.3.1 of this Operating Manual
- PA Pulser Receiver refer to paragraph 5.3.3 of this Operating Manual. The difference is in the incidence angle manipulation range only: –89...+89 deg for linear array equipped / not equipped with delay line vs 35...80 deg for wedged linear array
- Imaging and recording B-Scan cross sectional imaging and 3D data recording through linear scanning (C-Scan, Top, and Side Views) – refer to paragraph 5.3.4.1 of this Operating Manual. It is necessary just to note that incidence angle may be manipulated over wider range and dual mode of Pulsing / Receiving with partially of fully separated emitting and receiving aperture is allowed for linear array equipped / not equipped with delay line vs wedged linear array
- Imaging and recording Sector Scan cross sectional imaging and 3D data recording through linear scanning (C-Scan, Top, and Side Views) refer to paragraph 5.3.4.1 of this Operating Manual. It is necessary just to note that incidence angle may be manipulated over wider range and dual mode of Pulsing / Receiving with partially of fully separated emitting and receiving aperture is allowed for linear array equipped / not equipped with delay line vs wedged linear array

#	Item	Order Code (Part ##)	Note
	PA-2M8E1P - LINEAR ARRAY Frequency: 2 MHz Pitch Size: 1 mm Number of Elements: 8 Elevation: 9 mm	S 4922104376	Mark on the probe 104376
	PA-4M16E0.5P - LINEAR ARRAY Frequency: 4 MHz Pitch Size: 0.5 mm Number of Elements: 16 Elevation: 9 mm	S 4922104377	Mark on the probe 104377
	V20PA-8/16 - 20 mm delay line for S 4922104376 and S 4922104377 probes	S 4922104681	
	V40PA-8/16 - 40 mm delay line for S 4922104376 and S 4922104377 probes	S 4922104700	
	PA-5M32E0.5P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 0.5 mm Number of Elements: 32 Width (Elevation): 10 mm	S 4922104379	Mark on the probe 104379
	PA-5M16E1P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 1 mm Number of Elements: 16 Elevation: 10 mm	S4922105503	Mark on the probe 105503
	PA-7.5M32E0.5P - LINEAR ARRAY Frequency: 7.5 MHz Pitch Size: 0.5 mm Number of Elements: 32 Elevation: 10 mm	S 4944109464	Mark on the probe 109464
	V20PA-32 - 20 mm delay line for S 4922104379, S4922105503, and S 4944109464 probes	S 4922104682	
	V40PA-32 - 40 mm delay line for S 4922104379, S4922105503, and S 4944109464 probes	S 4922104701	

Typical PA probes and delay lines are listed below

-

#	Item	Order Code (Part ##)	Note
	PA-5M64E1.3P - LINEAR ARRAY for inspection of composites with built-in delay line ("solid" water) Frequency: 5 MHz Pitch Size: 1.3 mm Number of Elements: 64 Width (Elevation): 8 mm	S 4922104678	
	PA-5M64E1P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 1 mm Number of Elements: 64 Width: 10 mm	S 4922104381	Mark on the probe 104381
12	V20PA-64 - 20 mm delay line for S 4922104381 probe	S 4922104683	
	V40PA-64 - 40 mm delay line for S 4922104381 probe	S 4922104702	
	PA-2.25M16E1P - LINEAR ARRAY Frequency: 2.25 MHz Pitch Size: 1 mm Number of Elements: 16 Elevation: 13 mm	S 4922105504	Mark on the probe 105504
	V20PA-16/1 - 20 mm delay line for S 4922105504 probe	S 4922104684	
	PA-2.25M16E1.5P - LINEAR ARRAY Frequency: 2.25 MHz Pitch Size: 1.5 mm Number of Elements: 16 Elevation: 19 mm	S 4922105505	Mark on the probe 105505
17	V20PA-16/1.5 - 20 mm delay line for S 4922105505 probe	S 4922104685	

5.5. Optional SW Packages and Utilities

5.5.1. Options Menu

Options menu screen is presented below

Kis	CDM	볼륨 Lateral Scanning	Expert
Expert CU	VLFS	VLFS CU	Matrix Delay Line
Matrix Wedge	第 Multi Group	Reserved	Reserved
Reserved	Reserved	Reserved	Reserved
Back			

To run selected optional SW package click on it's icon. Click on or press **Esc** to return to the menu of PA modalities modes

5.5.2. Linear Array PA Probes

5.5.2.1. K_{Is} Optional SW Utility – Delta Technique



Delta Technique is based on shear wave insonifying defects and analyzing both direct shear wave echo and diffracted mode converted longitudinal wave echo. Delta Technique is mainly applicable to the evaluation of detected defects if it is necessary to characterize them as either sharp (crack) or volumetric (porosity, slag, etc). In the **ISONIC 2009 UPA Scope** Delta Technique has been implemented with use of single wedged linear array probe through K_{ls} optional SW utility providing simultaneous observation and evaluation of both echoes

On start it is necessary to define new wedged linear array probe or select an existing one in the instrument's database – this procedure is identical to the described in the paragraph 5.3.1 of this Operating Manual

<u>At the first evaluation step</u> **ISONIC PA Pulser Receiver** to provide indication of the maximized direct shear wave echo from the reflector under evaluation. The following preliminary settings are required:

#	Parameter or Mode	Setting	
1	Pulser Mode	SINGLE	
2	Aperture	$4 \le Aperture \le N/2$ whereas N is total Number Of Elements in the linear array probe	
3	Incidence Angle	According to inspection procedure	
4	USVelocity	Equal to the actual value of shear wave ultrasound velocity in the object under test	
5	Pulse Width, Firing	Pulse Width and Firing Level settings to optimize signal to noise ratio	
	Level	Pulse Width to be around 1/F where F is frequency of PA probe	
6		Filter and Low Cut and High Cut settings to match with frequency of PA probe to	
	High Cut Frequencies	optimize signal to noise ratio	
7	Display	Display setting may be either Full, RF, PosHalf, or NegHalf – follow requirements the	
		inspection procedure	
8	Surface Alignment	ON	
9	aSwitch	ON	
10	bSwitch	OFF	

Then maximize shear wave echo from defect under evaluation and:

- manipulate Gain to bring the echo amplitude to 80...100% of the A-Scan height
- manipulate Range to bring the echo to horizontal position of 80% of the A-Scan width
- place Gate A over the echo
- save current settings into a *.par file,

for that purpose click on swe or press **F11** then click on

Current Pulser Receiver

Continue holding of PA Probe in the position of receiving maximized shear

wave echo and click on

Shift + **Enter** to proceed to the second evaluation step

At the second evaluation step **ISONIC PA Pulser Receiver** to provide indication of the diffracted mode converted longitudinal wave echo from the reflector under evaluation whilst PA Probe remains in the position found at the *first evaluation step*. For that purpose:

 load *.par file just saved at the first evaluation step – for that purpose

click on or press **F12** then click



- set aSwitch to OFF and bSwitch to ON
- switch Pulser Mode to DUAL and enter RECEIVE submenu

1

It is a special unique feature of **ISONIC 2009 UPA Scope** instrument utilized in K_{Is} optional SW utility that for **DUAL** setting of **Pulser Mode** it is possible to control **USVelocity** settings for the emitting and receiving aperture independently on each other:

- USVelocity setting in the BASICS and EMIT submenu defines type of wave to be emitted and A-Scan time base
- USVelocity setting in the RECEIVE submenu defines type of wave for the received signals





- in the RECEIVE submenu set USVelocity equal to longitudinal wave velocity in the material, then manipulate incidence angle (and Focal Distance on case of Thickness Correction = OFF) for the receiving aperture to provide matching of focal points for emitting and receiving – for above-provided settings the diffracted mode converted longitudinal wave echo from the reflector under evaluation to appear to horizontal position of approximately 60% of the A-Scan width
- switch to BASICS submenu and manipulate Gain to bring the echo to 80...100% of the A-Scan height
- place Gate B over the echo

Current Pulser Recei

save current settings into a *.par file,

for that purpose click on swe or press **F11** then click on

Continue holding of PA Probe in the position of receiving maximized shear

wave echo and click on **I** or press **Shift** + **Enter** to proceed to the *third evaluation step*

At the *third evaluation step* it is provided indication of both **A-Scans** on one screen through implementation of both created focal laws in a loop sequence. Value K_{Is} representing ratio between longitudinal and shear wave echoes is determined in indicated in the corresponding display window – that is quantitative parameter for the distinguishing between firmly sharp reflectors ($K_{Is} \ge -20dB$) and volumetric reflectors ($K_{Is} \le -30 \ dB$)



5.5.2.2. CDM Optional Utility – Sizing Of Near Surface Cracks (Crack Depth Measurement)



CDM optional SW utility of **ISONIC 2009 UPA Scope** instrument is dedicated to precise determining of the depth for cracks visible on the outer surface of various objects – pressure vessels, heavy thickness pipes, etc. For that purpose it is provided longitudinal wave insonification through wall cross section of object under test, receiving and imaging of tip diffraction echo along with back-wall echo and lateral wave signal, and precise sizing of the crack under evaluation through automatic computations based on measured time of flight for the above signals; 5 MHz and 2 MHz 64- or 32-elements linear arrays with straight delay lines either regular or special to be used. On start it is necessary to define new linear array probe with delay line or select an existing one in the instrument's database – this procedure is identical to the described in the paragraph 5.3.1 of this Operating Manual

In the **CDM Setup – Step 1** screen **ISONIC PA Pulser Receiver** to provide indication of the back-wall echo. The following preliminary settings are required:

#	Parameter or Mode	Setting	
1	Pulser Mode	DUAL	
2	USVelocity	Equal to the actual value of longitudinal wave ultrasound velocity in the object under	
		test	
3	EMIT Aperture	N/4 whereas N is total Number Of Elements in the linear array probe	
4	EMIT Start	1	
5	RECEIVE Aperture	N/4 whereas N is total Number Of Elements in the linear array probe	
6	RECEIVE Start	¾×N + 1	
7	Surface Alignment	ON	
8	Thickness Correction	ON	
9	Thickness	To be equal to actual wall thickness WT	
10	Emitter Skip	0.5	
11	Receiver Skip	0.5	
12	EMIT Focal Depth	To be equal to actual wall thickness WT	
13	RECEIVE Focal Depth	To be equal to actual wall thickness WT	
14	EMIT Incidence Angle	> 0; To be calibrated synchronously with RECEIVE Incidence Angle by such a way	
		that focal points for emitting and receiving aperture will match on the bottom surface:	
		EMIT Incidence Angle = – RECEIVE Incidence Angle	
15	RECEIVE Incidence	< 0; To be calibrated synchronously with EMIT Incidence Angle by such a way that	
	Angle	focal points for emitting and receiving aperture will match on the bottom surface:	
		RECEIVE Incidence Angle = – EMIT Incidence Angle	
16	Pulse Width, Firing	Pulse Width and Firing Level settings to optimize signal to noise ratio	
	Level	Pulse Width to be around 1/F where F is frequency of PA probe	
17	Filter, Low Cut, and	Filter and Low Cut and High Cut settings to match with frequency of PA probe to	
	High Cut Frequencies	optimize signal to noise ratio	
18	Display	Display setting may be either Full, RF, PosHalf, or NegHalf - follow requirements the	
		inspection procedure	
19	aSwitch	ON	
20	bSwitch	OFF	
21	Meas Mode	Flank	

Upon preliminary settings are completed place PA probe onto the object under test outside of the crack area then:

- obtain back wall echo and calibrate
 Gain to bring echo amplitude to
 100% of A-Scan height
- set Range to provide appearance of back echo at approximately 90% of A-Scan
- cover back echo by Gate A
- save current settings into a *.prs file,

for that purpose click on save or press **F11** then click on current Pulser Receiver

Continue holding of PA Probe in the position of receiving back wall echo and

click on **I** or press **Shift** + **Enter** to proceed to the next **CDM Setup** – **Step 2** screen:

- load just saved *.prs file for that purpose click on or press F12
- then click on
- increase Gain by 30 dB
- set aSwitch to OFF

On completion continue holding of PA Probe in the position of receiving back

wall echo and click on or press Shift + Enter to proceed to the CDM screen. CDM screen is used for precise measurements of crack depth upon tip of the crack has been localized. So at that stage it is necessary to pass through CDM screen to the next one allowing localizing tip of crack easily – so simply

click on **I** or press **Shift** + **Enter**



The **ISONIC 2009 Crack Depth Meter** screen becomes active. At this stage **ISONIC 2009 UPA Scope** instrument divides narrow area under the centerline of PA probe into a number of grids and implements several focal laws to insonify each grid. For every focal law (every greed):

- emitting aperture generates longitudinal wave focused into the center of certain greed
- receiving aperture is focused to the center of the greed for longitudinal wave signal
- A-Scan range is calibrated automatically by such a way that the signal from possible obstacle located at the center of the greed will be situated at 50% of A-Scan width
- Gate A position is calibrated automatically to cover possible signal
- B-Scan image is formed through filling grids with color corresponding to signal amplitude within the Gate A

A-Scans for each focal law may be observed / marked along with implemented ray trace through manipulating cursor over the grids

composing **B-Scan** – use control

Whilst probe it placed over the area with no defect on the **B-Scan** there are clearly distinguished grids corresponding to receiving of back wall echo and lateral wave signals



A-Scan and ray trace corresponding to receiving back wall echo



A-Scan and ray trace corresponding to receiving lateral wave signal



On placing probe above crack to be sized at rectangle to the crack direction on outer surface lateral wave signal will be suppressed significantly whilst crack's tip diffraction signal will be received and corresponding grids will be distinguished clearly on the **B-Scan**

Place cursor over the grid representing crack's tip diffraction signal and maximize it through back and forward manipulation of PA Probe at rectangle to the crack line. On reaching maximized crack's tip diffraction signal mark the corresponding grid and take readings from



To size crack depth precisely remember readings as **A0** and **FD0** then click on

or press or press **Esc** – this will

return to **CDM** screen then click on or press or press **Esc** again – this will return to **CDM Setup – Step 2** screen

$\textcircled{1}{2}$

Other procedures in the **Crack Depth Meter** screen such as storing **B-Scan** into a file / upload from a file, Freeze / Unfreeze, etc are identical to already described – refer to paragraph 5.3.4.1.3 of this Operating Manual



A-Scan and ray trace corresponding to receiving suppressed lateral wave signal ISONIC 2009 PA - Crack Depth Meter







Whilst in CDM Setup – Step 2 screen:

- Set EMIT Incidence Angle to A0 ٠
- Set EMIT Focal Depth to FD0 ٠
- Set RECEIVE Incidence Angle to ۲ **A0**
- Set RECEIVE Focal Depth to FD0 ۲
- maximize crack's tip diffraction signal ٠ through back and forward manipulation of PA Probe at rectangle to the crack line
- set **bSwitch** to ON then cover crack's tip diffraction signal by Gate В



On completion click on Shift + Enter – on the CDM screen it will be indicated:

- two **A-Scans** for focal laws one for ٠ the receiving of back echo; second for the receiving of the maximized crack's tip diffraction signal
- 5 digital readouts as below: ٠

T(A)	-	time of flight for back wall echo
D(A)	-	measured wall thickness
T(B)	-	time of flight for crack's tip diffraction signal
D(B)	-	measured crack depth
∆(D)	-	remaining wall thickness under the crack's tip



5.5.2.3. Lateral Scanning Optional Inspection SW Package



LATERAL SCANNING optional SW package of ISONIC 2009 UPA Scope instrument relates to the inspection of various objects with use of wedged linear array probes providing generating and receiving of either guided, surface, or shear waves. Linear arrays are situated on the wedge laterally so that incidence angle is fixed being defined by wedge geometry only. On the other hand it is possible swiveling of ultrasonic beam in the material electronically through controlling azimuth direction for emitting / receiving aperture. Also if the aperture size is less than total number of elements of linear array then it is possible to perform linear scanning of the material in lateral direction electronically

5.5.2.3.1. Probe selection

On start it is necessary to define new wedged linear array probe or select an existing one in the instrument's database – this procedure is identical to the described in the paragraph 5.3.1 of this Operating Manual. On completion click





5.5.2.3.2. ISONIC PA Pulser Receiver

To control **ISONIC PA Pulser Receiver** refer to paragraph 5.5.3 of this Operating Manual and notes below

- □ **Azimuth** is setting to control swiveling of ultrasonic beam
- □ **Top**, **Side**, and **End** views of probe placed onto material and ultrasonic beam in the material may be selected for viewing through click on



varying depending on the next available view)



1 Linear Scan

2 Azimuth Scan

3 Combined Scan

4 Back

R

5.5.2.3.3. Modes of Lateral Scanning and Imaging

There are two modes of lateral scanning possible:

- □ Linear click on –
- Azimuth click on

Linear scanning at fixed swiveling angle (azimuth) is performed through electronic shift of predetermined aperture within entire linear array comprising more elements than aperture size

Azimuth scanning is through varying of swiveling angle (azimuth) in a certain range whilst the aperture is fixed

5.5.2.3.4. Linear Scan

It is recommended to perform *Gain per Shot Correction* prior to Linear Scan – the procedure is identical to the described in the paragraph 5.3.4.1.2 of this Operating Manual

Whilst **Linear Scan** screen is active **ISONIC 2009 UPA Scope** produces the **CB-Scan** image is produced. Control of the instrument is the same as it is described in the paragraph 5.3.4.1.3 of this Operating Manual



5.5.2.3.5. Azimuth Scan

It is recommended to perform *Gain per Swiveling Angle Correction* prior to Linear Scan – the procedure is identical to the described in the paragraph 5.3.4.1.2 of this Operating Manual

Whilst **Linear Scan** screen is active **ISONIC 2009 UPA Scope** produces the **CB-Scan** image is produced. Control of the instrument is the same as it is described in the paragraph 5.3.4.1.3 of this Operating Manual



Movie illustrating operating of **ISONIC 2009 UPA Scope** whilst running **Lateral Scanning** SW is available for viewing / download at http://www.sonotronndt.com/PDF/OM2009/LATERAL.wmv

5.5.2.4. EXPERT – Optional Inspection SW Package For Welds



EXPERT optional SW package of **ISONIC 2009 UPA Scope** instrument is dedicated to the inspection of welds having planar cross section. It is applicable to planar and circumferential butt welds, corner welds, nozzles, tee welds, and the like. On start it is necessary to define new wedged linear array probe or select an existing one in the instrument's database – this procedure is identical to the described in the paragraph 5.3.1 of this Operating Manual. Next step is selection of the way to insonify cross section of the weld – there are 2 ways available:

B-Scan and Sector Scan (S-Scan)



5.5.2.4.1. B-Scan

#	Task	Instruction
1	Calibration of ISONIC PA Pulser Receiver	Refer to paragraph 5.3.4.1.1 of this Operating Manual
2	Calibration of Gain Per Shot Correction	Refer to paragraph 5.3.4.1.2 of this Operating Manual
3	Weld definition and selection of probe position	There is a number for parameters characterizing weld geometry to be keyed in. Then probe position to be selected to provide necessary coverage; said coverage is clearly indicated
		On completion click on erress Shift + Enter to proceed with TTGI B-Scan
		For more instructions on weld cross section geometry settings refer to paragraph 5.5.2.4.3 of this Operating Manual

#	Task	Instruction		
4	TTGI B-Scan	TTGI B-Scan represents actual coverage of the material. To control instrument in that screen refer to paragraphs 5.3.4.1.3 and 5.3.4.1.4 this Operating Manual		
		Fine State Image: State Ima		
		aswitch ON ON ON ON ON ON ON ON ON ON		
		2 aWidth 1 <td< td=""></td<>		
		ņmm 1		
		22mm		
5	3D data recording through linear scanning (C-Scan , Top and Side Views)	To control instrument in that screen refer to paragraph 5.3.4.1.5 of this Operating Manual. In addition it is necessary to define the region of interest as either including heat affected zone (HAZ) or not through		
		checking corresponding option		
		CScan		
		240 mm 200 5 Scan Time 10 s 5 10 s 5		
		Crocders Crocd		
		Coloring Precudo2		
		22mm		

5.5.2.4.2. Sector-Scan

#	Task	Instruction
1	Calibration of ISONIC PA Pulser Receiver	Refer to paragraph 5.3.4.2.1 of this Operating Manual
2	Calibration of Gain Per Angle Correction	Refer to paragraph 5.3.4.2.2 of this Operating Manual
3	Weld definition and selection of probe position	There is a number for parameters characterizing weld geometry to be keyed in. Then probe position to be selected to provide necessary coverage; said coverage is clearly indicated

#	Task	Instruction
4	TTGI Sector-Scan	TTGI Sector-Scan represents actual coverage of the material. To control instrument in that screen refer to paragraphs 5.3.4.2.3 and 5.3.4.2.4 of this Operating Manual Sector scan
		A CAR A Measurements:
		aSwitch
		+ + + + + + + + + + + + + + + + + + +
		20.1 mm Amplitude 010 Current
		Coloring 10 aThreshold I
		Zoom X1 X2 X3 Flank
		0mm
		22mm
5	3D data recording through linear scanning (C-Scan , Top and Side Views)	To control instrument in that screen refer to paragraph 5.3.4.2.5 of this Operating Manual. In addition it is necessary to define the region of interest as either including heat affected zone (HAZ) or not through
		checking corresponding option
		CScan
		And the second sec
		Sean Type Time 10 Scan Length 10 Scan Length
		260 mm 2 0 50 100 150 200 250
		25 s s s s s s s s s s s s s s s s s s s
		Encoders
		Certault Certault Certault Certault Certault Certault Certault Side View
		CHARCE CHARCE C Enable C Disable
		Coloring Pseudo2
		Clear Save Open
		Ciscan Biscan ON ON
		Back OFF OFF 22mm

5.5.2.4.3. Weld Cross Section Geometry Settings

EXPERT SW option is suitable for the inspection of welds of various geometries. To provide the required coverage and imaging the weld parameters to be entered accordingly, typical examples are presented below
















5.5.2.5. EXPERT CU – Optional Inspection SW Package For Tubular Objects, Rods, and Welds



EXPERT CU optional SW package of **ISONIC 2009 UPA Scope** instrument is dedicated to the inspection of:

- tubular objects
- rods

٠

- welded joints of several types such as:
 - o longitudinal welds in pipes, pressure vessels, and the like
 - o butt welds between spherical shape components
 - o TKY welds

5.5.2.5.1. Circumferential Insonification

Whilst running **EXPERT CU** insonification of object under test is performed circumferentially. For that purpose linear array probes equipped with contoured wedges are suitable, the exemplary list of probes is present below

#	Item	Order Code (Part ##)	Note
1	PA-2M8E1P - LINEAR ARRAY Frequency: 2 MHz Pitch Size: 1 mm Number of Elements: 8 Elevation: 9 mm	S 4922104376	Mark on the probe 104376
2	PA-4M16E0.5P - LINEAR ARRAY Frequency: 4 MHz Pitch Size: 0.5 mm Number of Elements: 16 Elevation: 9 mm	S 4922104377	Mark on the probe 104377
3	VKPA-8/16 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922104376 and S 4922104377 probes	S 4922104378	Suitable for OD ≥ 1000 mm Linear array probes equipped with that wedge are defined in the instrument database as 104378W36 104377W36
4	VKPA-8/16 CU XXX - 36° wedge (55° central angle for shear wave in low carbon steel) - circumferentially contoured for XXX mm OD /// for S 4922104376 and S 4922104377 probes	S 4922104378 CUC XXX	Suitable for OD < 1000 mm Linear array probes equipped with that wedge are defined in the instrument database as 104378W36CUCxxx 104377W36 CUCxxx whereas xxx is OD expressed in mm
5	PA-5M32E0.5P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 0.5 mm Number of Elements: 32 Width (Elevation): 10 mm	S 4922104379	Mark on the probe 104379
6	PA-5M16E1P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 1 mm Number of Elements: 16 Elevation: 10 mm	\$4922105503	Mark on the probe 105503
7	PA-7.5M32E0.5P - LINEAR ARRAY Frequency: 7.5 MHz Pitch Size: 0.5 mm Number of Elements: 32 Elevation: 10 mm	S 4944109464	Mark on the probe 109464
	VKPA-32 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922104379, S4922105503, and S 4944109464 probes	S 4922104380	Suitable for OD ≥ 1000 mm Linear array probes equipped with that wedge are defined in the instrument database as □ 104379W36 □ 105503W36 □ 109464W36
9	VKPA-32 CUC XXX - 36° wedge (55° central angle for shear wave in low carbon steel) - circumferentially contoured for XXX mm OD /// for S 4922104379, S4922105503, and S 4944109464 probes	S 4922104380 CUC XXX	Suitable for OD < 1000 mm Linear array probes equipped with that wedge are defined in the instrument database as 104379W36CUCxxx 105503W36CUCxxx 109464W36CUCxxx whereas xxx is OD expressed in mm

#	ltem	Order Code (Part ##)	Note	
	PA-5M64E1P - LINEAR ARRAY Frequency: 5 MHz Pitch Size: 1 mm Number of Elements: 64 Width: 10 mm	S 4922104381	Mark on the probe 104381	
	VKPA-64 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922104381 probe	S 4922705119	Suitable for OD ≥ 1200 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 104381W36	
	VKPA-64 CUC XXXX - 36° wedge - 36° wedge (55° central angle for shear wave in low carbon steel) - circumferentially contoured for XXXX mm OD /// for S 4922104381 probe	S 4922705119 CUC XXXX	Suitable for OD < 1200 mm Linear array probe equipped with that wedge are defined in the instrument database as 104381W36CUCxxxx whereas xxxx is OD expressed in mm	
	PA-2.25M16E1P - LINEAR ARRAY Frequency: 2.25 MHz Pitch Size: 1 mm Number of Elements: 16 Elevation: 13 mm	S 4922105504	Mark on the probe 105504	
	VKPA-16/1 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922105504 probe	S 4922104679	Suitable for OD ≥ 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as D 105504W36	
	VKPA-16/1 CUC XXX - 36° wedge (55° central angle for shear wave in low carbon steel) - circumferentially contoured for XXX mm OD /// for S 4922105504 probe	S 4922104679 CU XXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 105504W36CUCxxx whereas xxx is OD expressed in mm	
	PA-2.25M16E1.5P - LINEAR ARRAY Frequency: 2.25 MHz Pitch Size: 1.5 mm Number of Elements: 16 Elevation: 19 mm	S 4922105505	Mark on the probe 105505	
	VKPA-16/1.5 - 36° wedge (55° central angle for shear wave in low carbon steel) for S 4922105505 probe	S 4922104680	Suitable for OD ≥ 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 105505W36	
	VKPA-16/1.5 CUC XXX - 36° wedge (55° central angle for shear wave in low carbon steel) - circumferentially contoured for XXX mm OD /// for S 4922105505 probe	S 4922104680 CUC XXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as ☐ 105505W36CUCxxx whereas xxx is OD expressed in mm	
	PA-1.5M16E1P - LINEAR ARRAY Frequency: 1.5 MHz Pitch Size: 1 mm Number of Elements: 16 Elevation: 12 mm	S 4922107553	Mark on the probe 107553	
	VPKA-38-16-1-21 - 38° wedge (59° central angle for shear wave in low carbon steel) for S 4922107553 probe	S 4944262021	Suitable for OD ≥ 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 107553W39-21	
	VPKA-38-16-1-12 - 38° wedge (59° central angle for shear wave in low carbon steel) for S 4922107553 probe	S 4944262012	Suitable for OD \geq 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as \Box 107553W39-12	
	VPKA-38-16-1-21 CUC XXX - 38° wedge (59° central angle for shear wave in low carbon steel) - circumferentially contoured for XXX mm OD /// for S 4922107553 probe	S 4944262021 CUC XXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 107553W39-21CUCxxx whereas xxx is OD expressed in mm	
	VPKA-38-16-1-12 CUC XXX - 38° wedge (59° central angle for shear wave in low carbon steel) - circumferentially contoured for XXX mm OD /// for S 4922107553 probe	S 4944262012 CUC XXX	Suitable for OD < 1000 mm Linear array probe equipped with that wedge are defined in the instrument database as □ 107553W39-12CUCxxx whereas xxx is OD expressed in mm	

On start it is necessary to define new wedged linear array probe or select an existing one in the instrument's database – this procedure is identical to the described in the paragraph 5.3.1 of this Operating Manual.

5.5.2.5.2. ISONIC PA Pulser Receiver – Circumferential Insonification

ISONIC PA Pulser Receiver to be calibrated as it is described in the paragraph 5.3.3 of this Operating Manual with considering geometry of object under test – curvature of outer surface and wall thickness

For the inspection of rods key in

Thickness = 1/2 Diameter

whereas **Diameter** is outside diameter of the rod. In that case **Focal Depth** setting and reflector depth readings **t(A)**, **t(B)** are defined by the instrument automatically according to the sketch below:





Other settings of **ISONIC PA Pulser Receiver** to be according to paragraph 5.3.4.2.1 of this Operating Manual Movie illustrating electronic beam steering within the rod is available for viewing / download at http://www.sonotronndt.com/PDF/OM2009/ROD_SHEAR.wmv

For the inspection of wall of tubular object or weld key in outside diameter value as the **Diameter** and wall thickness value as **Thickness**. In that case **Focal Depth** setting and reflector depth readings **t(A)**, **t(B)** are defined by the instrument automatically according to the sketch below:





Other settings of **ISONIC PA Pulser Receiver** to be according to paragraph 5.3.4.2.1 of this Operating Manual Movie illustrating electronic beam steering within the tube wall is available for viewing / download at http://www.sonotronndt.com/PDF/OM2009/TUBULAR_SHEAR.wmv

On completion of calibration click on **I** or press **Shift** + **Enter**

5.5.2.5.3. Inspection of Rods and Tube Walls



#	Task	Instruction	
1	Calibration of Gain Per Angle Correction	Refer to paragraph 5.3.4.2.2 of this Operating Manual	
2	TTGI Sector-Scan - rods	TTGI Sector-Scan represents actual coverage of the material. To control instrument in that screen refer to paragraphs 5.3.4.2.3 and 5.3.4.2.4 of this Operating Manual Sector Scan Gain Gain	
3	3D data recording through linear scanning (C-Scan, Top and Side Views) - rods	To control instrument in that screen refer to paragraph 5.3.4.2.5 of this Operating Manual	

#	Task	Instruction
4	TTGI Sector-Scan – tube wall	TTGI Sector-Scan represents actual coverage of the material. To control instrument in that screen refer to paragraphs 5.3.4.2.3 and 5.3.4.2.4 of this Operating Manual
		Sector Scan
		1 Gain 56 dB 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
		2 astart 30 mm 2 2 b 22.93 us Save Open Print Depth Depth Avridith Augustus astart Augustus astart Au
		Coloring 10 at Inveshold 20% I at a second at a secon
		50 550
		100
5	3D data recording through linear	To control instrument in that screen refer to paragraph 5.3.4.2.5 of this
5	scanning (C-Scan , Top and Side Views) – tube wall	Operating Manual
		10 Scan Length 10 10 200 5 Scan Time 15 100 150 200
		Time-Walt 3 s Encoders Default
		Coloring 5800
		Preudo2 Clear Save Open Mak
		Back OFF OFF 100

5.5.2.5.4. Inspection of Welds



Task	Instruction
Calibration of Gain Per Angle Correction	Refer to paragraph 5.3.4.2.2 of this Operating Manual
Weld definition and selection of probe position	There is a number for parameters characterizing weld geometry to be keyed in. Then probe position to be selected to provide necessary coverage; said coverage is clearly indicated
	Correction Weld definition and selection of probe

#	Task	Instruction
3	TTGI Sector-Scan	TTGI Sector-Scan represents actual coverage of the material. To control instrument in that screen refer to paragraphs 5.3.4.2.3 and 5.3.4.2.4 of this Operating Manual
		2 Gain Measurements: Fip Sides Freeze
		ON Z TOF Save Open Print
		18 mm 3 Depth Mark
		Coloring 10 aThreshold V(A)
		Pseudo2 20% IS 15.83 dB Angle 47.2° ✓ Paint Zoom X1 X2 X3
4	3D data recording through linear scanning (C-Scan , Top and Side Views)	To control instrument in that screen refer to paragraph 5.3.4.2.5 of this Operating Manual. In addition it is necessary to define the region of interest as either including heat affected zone (HAZ) or not through
		checking corresponding option C Divable
		Scan Type
		10 Scan Length 210 mm
		5 Scan Time 15 S Time Wait 5 Scan Time Time Wait 5 Scan Time 5
		Default Image: Constraint of the second se
		Coloring Preudo2

5.5.2.5.5. Weld Cross Section Geometry Settings

EXPERT CU SW option is suitable for the inspection of welds of various geometries. To provide the required coverage and imaging the weld parameters to be entered accordingly, typical examples are presented below. Also refer to paragraph 5.5.2.4.3 of this Operating Manual





5.5.2.6. VLFS – Optional Inspection SW Package



VLFS (Vertical Line Focusing Scan) optional SW package of ISONIC 2009 UPA Scope instrument is dedicated to the inspection of ERW seams with planar cross section and the like, for example ERW seams between pipes, rails, etc It is a special feature of VLFS mode of operation that focusing of every beam composing **B-Scan** or **Sector Scan** image of the region of interest (**ROI**) is performed along vertical line.welds having planar cross section. On start it is necessary to define new wedged linear array probe or select an existing one in the instrument's database – this procedure is identical to the described in the paragraph 5.3.1 of this Operating Manual. Next step is selection of the way to insonify **ROI** – there are 2 ways



5.5.2.6.1. B-Scan

#	Task	Instruction
1	Calibration of ISONIC PA Pulser Receiver	Refer to paragraph 5.3.4.1.1 of this Operating Manual
2	Calibration of Gain Per Shot Correction	Refer to paragraph 5.3.4.1.2 of this Operating Manual
3	Calibration of Gain Per Shot Correction Defining of ROI and selection of the Probe Position	Refer to paragraph 5.3.4.1.2 of this Operating Manual Width of ROI is defined symmetrically for the vertical focused line. Then probe position to be selected to provide necessary coverage of ROI , which is clearly indicated
		On completion click on Next or press Shift + Enter to proceed with TTGI B-Scan

#	Task	Instruction
4	TTGI B-Scan	TTGI B-Scan represents actual coverage of the ROI. To control instrument in that screen refer to paragraphs 5.3.4.1.3 and 5.3.4.1.4 of this Operating Manual
5	3D data recording through linear scanning (C-Scan, Top and Side Views)	To control instrument in that screen refer to paragraph 5.3.4.1.5 of this Operating Manual

5.5.2.6.2. Sector-Scan



#	Task	Instruction	
4	TTGI Sector-Scan	Instruction TrGI Sector-Scan represents actual coverage of the ROI. To control instrument in that screen refer to paragraphs 5.3.4.2.3 and 5.3.4.2.4 of this Operating Manual Sector Scan Sector Sc	
5	3D data recording through linear scanning (C-Scan, Top and Side Views)	To control instrument in that screen refer to paragraph 5.3.4.2.5 of this Operating Manual	

5.5.2.7. VLFS CU – Optional Inspection SW Package



VLFS CU (Vertical Line Focusing Scan of CUrved objects) optional SW package of **ISONIC 2009 UPA Scope** instrument is dedicated to the inspection of ERW seams with curved cross section and similar objects providing **Sector Scan** imaging of the region of interest (**ROI**). On start it is necessary to define new wedged linear array probe or select an existing one in the instrument's database – refer to paragraphs 5.3.1 and 5.5.2.5.1 of this Operating Manual. Further steps are described below

#	Task	Instruction	
1	Calibration of ISONIC PA Pulser Receiver	Refer to paragraphs 5.3.4.2.1 and 5.5.2.5.2 of this Operating Manual	
2	Calibration of Gain Per Angle Correction	Refer to paragraph 5.3.4.2.2 of this Operating Manual	
3	Defining of ROI and selection of the Probe Position	Refer to paragraphs 5.3.4.2.1 and 5.5.2.5.2 of this Operating Manual	

#	Task	Instruction
4	TTGI Sector-Scan	TTGI Sector-Scan represents actual coverage of the ROI. To control instrument in that screen refer to paragraphs 5.3.4.2.3 and 5.3.4.2.4 of this Operating Manual Sector Scan Sector Scan
5	3D data recording through linear scanning (C-Scan, Top and Side Views)	To control instrument in that screen refer to paragraph 5.3.4.2.5 of this Operating Manual

5.5.2.8. Multi-Group – Optional Inspection SW Utility



Multi-Group optional SW package of **ISONIC 2009 UPA Scope** instrument allows implementation of several (up to 5) various insonification schemes simultaneously with use of differently configured groups of elements of wedged linear array probe. Each insonification scheme to be implemented with the same filter settings of **ISONIC PA Pulser Receiver**. Geometry settings (thickness, weld, curvature) if any, probe position, and **USVelocity** in the material as to be identical for all insonification schemes. Calibration for each insonification scheme to be performed in advance and the appropriate **B-Scan / Sector-Scan** files

either **TTGI** or not to be stored in advance in accordance with procedures described in the paragraphs 5.3.4.1, 5.3.4.2, 5.5.2.4 through 5.5.2.7 of this Operating Manual. Movie illustrating typical composing and implementation of multi-group insonification is available for viewing / download at http://www.sonotronndt.com/PDF/OM2009/MULTI_GROUP.wmv

5.5.3. Matrix Array PA Probes

No-multiplexing parallel architecture of **ISONIC 2009 UPA Scope** instrument allows using of up to 64elements matrix arrays probes. This makes it possible insonifying predefined volume in the object under test and obtaining 3D image of it's interior from fixed probe position without involving mechanical scanning

5.5.3.1. Matrix Delay Line 3D Scan L – Optional Inspection SW Package for Compression Wave Inspection



Matrix Delay Line 3D Scan L optional inspection SW package utilizes matrix array probes either equipped with delay line or directly contacted to object under test for compression wave inspection with 3D image data presentation

5.5.3.1.1. Database of Matrix Arrays With / Without Delay Line

It is necessary to define matrix array probe with / without delay line probe or select an existing one in the database first for further operation – refer to paragraph 5.3.1 of this Operating Manual

Whilst defining matrix array probe and for further operation 3D graphic presentation is very useful, to optimize 3D viewing use 3D toolbox:



It is also possible to control 3D view by mouse through placing cursor over the image:

- left mouse button press and hold followed by mouse motion allows moving of the imaged object in the desired direction
- right mouse button press and hold followed by mouse motion allows rotating of the imaged object in the desired direction



5.5.3.1.2. ISONIC PA Pulser Receiver for Matrix Arrays With / Without Delay Line

To control **ISONIC PA Pulser Receiver** refer to paragraph 5.5.3 of this Operating Manual and notes below

- 2D aperture setting Start and Aperture setting to be provided for both Width and Length directions
- 3D control of ultrasonic beam is performed through use of the following settings:
 - Incidence Angle
 - Rotation Angle
 - Focal Depth and Skip OR Focal Distance



The following settings to be provided **for 3D Scan L** mode of operation:

#	Parameter or Mode	Required Settings	Note
1	Pulser Mode	SINGLE	
2	Aperture Width	N_{W} whereas N_{W} is total $\textit{Number Of Elements}$ in the Width direction	recommended
3	Aperture Length	N_{L} whereas N_{L} is total $\textit{Number Of Elements}$ in the Width direction	recommended
4	Incidence Angle	0 deg	Only at the stage of setting Gain
5	Rotation Angle	0 deg	Only at the stage of setting Gain
6	Thickness Correction	ON	
7	Thickness	Equal to the actual value of material thickness	
8	Emitter / Receiver Skip	0.5	
9	Focal Depth	In accordance with the inspection procedure	
10	USVelocity	Equal to the actual value of ultrasound velocity in the object under test either for shear or longitudinal waves	
11	Gain	Gain setting to be performed according to inspection procedure providing required echo heights from defects to be detected	
12	DAC/TCG	DAC/TCG settings to meet requirements of inspection procedure	
13	Pulse Width, Firing Level	Pulse Width and Firing Level settings to optimize signal to noise ratio Pulse Width to be around 1/F where F is frequency of PA probe	To synchronize with Gain setting – finalize setting of Pulse Width and Firing Level before setting of the Gain
14	Filter, Low Cut, and High Cut Frequencies	Filter and Low Cut and High Cut settings to match with frequency of PA probe to optimize signal to noise ratio	To synchronize with Gain setting – finalize setting of Filter, Low Cut, and High Cut before setting of the Gain
15	Display	Display setting may be either Full , RF , PosHalf , or NegHalf – follow requirements the inspection procedure	
16	Surface Alignment	ON	
17	Range	Range setting is important at the stage of Gain and DAC setup only providing representation of all reflectors used for Gain and DAC calibration	

On completing click on I or press Shift + Enter

5.5.3.1.3. Region of Interest (ROI)

ROI is a part of volume of object under test under matrix array, which is defined through keying in of 3 values:

- □ ROI Width
- □ ROI Length
- ROI Start (counted as distance from contact surface of the material)

The last setting (ROI Height) is defined automatically:

ROI Height = Focal Depth – ROI Start

All dimensions are clearly shown on the sketch





5.5.3.1.4. 3D Scan L Mode of Inspection and Imaging

Typical **3D Scan L** screen is shown below. 3D image is provided through rendering of elementary volumes composing **ROI**; color of each elementary volume represents corresponding echo amplitude





Vertical size of 3D Scan L image depends on status of



①

Quantity of rendered elementary volumes depends on amplitude **Filter** settings, filtering level may vary between 0 to 130% of **A-Scan** height



①

It is possible to apply geometry filter to cut top and bottom part of **3D Scan L** image through dialogue activated by clicking on



Movie illustrating operating of **ISONIC 2009 UPA Scope** whilst running **3D Scan L** SW is available for viewing / download at <u>http://www.sonotronndt.com/PDF/OM2009/3D_SCAN_L.wmv</u>

5.5.3.2. Matrix Wedge 3D Scan S – Optional Inspection SW Package for Shear Wave Inspection



Matrix Wedge 3D Scan S optional inspection SW package utilizes wedged matrix array probes for shear wave inspection with 3D image data presentation

5.5.3.2.1. Database of Wedged Matrix Arrays

It is necessary to define new wedged matrix array probe or select an existing one in the database first for further operation – refer to paragraph 5.3.1 of this Operating Manual

Whilst defining matrix array probe and for further operation 3D graphic presentation is very useful, to optimize 3D viewing use 3D toolbox:



It is also possible to control 3D view by mouse through placing cursor over the image:

- left mouse button press and hold followed by mouse motion allows moving of the imaged object in the desired direction
- right mouse button press and hold followed by mouse motion allows rotating of the imaged object in the desired direction



5.5.3.2.2. ISONIC PA Pulser Receiver for Wedged Matrix Arrays

To control **ISONIC PA Pulser Receiver** refer to paragraph 5.5.3 of this Operating Manual and notes below

- 2D aperture setting Start and Aperture setting to be provided for both Width and Length directions
- □ **3D** control of ultrasonic beam is performed through use of the following settings:
 - Incidence Angle
 - Swiveling Angle
 - Focal Depth and Skip OR Focal Distance



The following settings to be provided **for 3D Scan S** mode of operation:

#	Parameter or Mode	Required Settings	Note
1	Pulser Mode	SINGLE	
2	Aperture Width	N_{W} whereas N_{W} is total $\textit{Number Of Elements}$ in the Width direction	recommended
3	Aperture Length	N_L whereas N_L is total <i>Number Of Elements</i> in the Width direction	recommended
4	Incidence Angle	A value within required varying range for incidence angle in accordance with the inspection procedure	Only at the stage of setting Gain
5	Swiveling Angle	0 deg	Only at the stage of setting Gain
6	Thickness Correction	ON	
7	Thickness	Equal to the actual value of material thickness	
8	Emitter / Receiver Skip	In accordance with the inspection procedure	Only at the stage of setting Gain
9	Focal Depth	In accordance with the inspection procedure	
10	USVelocity	Equal to the actual value of ultrasound velocity in the object under test either for shear or longitudinal waves	
11	Gain	Gain setting to be performed according to inspection procedure providing required echo heights from defects to be detected	
12	DAC/TCG	DAC/TCG settings to meet requirements of inspection procedure	
13	Pulse Width, Firing Level	Pulse Width and Firing Level settings to optimize signal to noise ratioPulse Width to be around 1/F where F is frequency of PA probe	To synchronize with Gain setting – finalize setting of Pulse Width and Firing Level before setting of the Gain
14	Filter, Low Cut, and High Cut Frequencies	Filter and Low Cut and High Cut settings to match with frequency of PA probe to optimize signal to noise ratio	To synchronize with Gain setting – finalize setting of Filter, Low Cut, and High Cut before setting of the Gain
15	Display	Display setting may be either Full , RF , PosHalf , or NegHalf – follow requirements the inspection procedure	
16	Surface Alignment	ON	
17	Range	Range setting is important at the stage of Gain and DAC setup only providing representation of all reflectors used for Gain and DAC calibration	

On completing click on I or press Shift + Enter

5.5.3.2.3. 3 D Scan S: Scanning Modes

There are two scanning and imaging modes available while running 3D Scan S SW packages:

 Vertical Plane Focusing Scanning (VPFS) – click on For that type of scanning focal points for each implemented focal law are situated in the same predetermined vertical plane; such way of insonification is suitable for the inspection of ERW joints and the like
 EXPERT – click on This type of insonification is suitable for the inspection of butt, corner, nozzle, tee- welds and the like





5.5.3.2.5. 3D Scan S: EXPERT – Inspection of Welds



Movie illustrating operating of **ISONIC 2009 UPA Scope** whilst running **3D Scan L** SW is available for viewing / download at <u>http://www.sonotronndt.com/PDF/OM2009/3D_SCAN_S.wmv</u>

5.6. Viewing And Processing Of Recorded Files – PA Modality 5.6.1. Posptorocessing on board ISONIC 2009 UPA Scope

ISONIC 2009 UPA Scope instrument is equipped with comprehensive viewing postprocessing tools for all types of inspection and calibration files. On entering postprocessing mode from **PA Modality Start Menu** (refer to paragraph 5.1 of this Operating Manual) ISONIC 2009 Explorer screen appears. To start postprocessing / viewing of the file double click on it's name



The following typical functions are provided at the postprocessing stage:

			File types			
Function	Gain per Angle / Gain per Shot Correction	Parametric file – calibration of ISONIC PA Pulser Receiver	2D Files – B- Scan, Tandem B- Scan, Sector Scan, CB- Scan	Multi-Group Files	3D Files – Top, Side, End Views captured with linear array probes through mechanical scanning	3D Files captured with matrix array probes
Viewing	Y	Y	Y	Y	Y	Y
Editing	Y	Y ±6 dB Gain manipulation	Y ±6 dB Gain manipulation	Y ±6 dB Gain manipulation	Y ±6 dB Gain manipulation	Y ±6 dB Gain manipulation
A-Scan and Gate based signal evaluation	NA	Y	Y	Y	N	Y
Play back of raw data A-Scan	NA	NA	Y	Y	Y	Y
Play Back of Raw data B-Scan, Sector Scan	NA	NA	NA	NA	Y	NA
Measuring projection dimensions of reflectors	NA	NA	Y	Y	Y	Y
Amplitude Filtering	NA	NA	Y	Y	Y	Y
Geometry filtering	NA	NA	NA	NA	Y	Y
Profiling (slicing) in 3 planes	NA	NA	NA	NA	Y	Y
3D presentation of the inspected volume with defects	NA	NA V - VES N	NA = NO NA = Not	NA	Y	Y

Postprocessing is implemented through intuitive interface, typical movies explaining various off-line operations are available for viewing / download at:

File Type	Postprocessing Movie Viewing / Download Link
Weld cross section – EXPERT Mode – TTGI Sectro Scan	http://www.sonotronndt.com/PDF/OM2009/TTGI S SCAN BUTT WELD PP.wmv
Weld Scanning – EXPERT mode – TTGI Sector Scan and 3D data Capturing	http://www.sonotronndt.com/PDF/OM2009/EXP_PP_BUTT_WELD_SCAN.wmv
B-Scan – composite material	http://www.sonotronndt.com/PDF/OM2009/STRAIGHT_B_SCAN.wmv
Scanning of composite material – B-Scan and 3D Data Capturing	http://www.sonotronndt.com/PDF/OM2009/STRAIGHT_B_SCAN_SC.wmv
Multi - Group	http://www.sonotronndt.com/PDF/OM2009/MGR_PP.wmv
Files created with use of matrix probes	http://www.sonotronndt.com/PDF/OM2009/MATRIX_PP.wmv

5.6.2. Posptorocessing in the PC

5.6.2.1. ISONIC 2009 PP Postprocessing Package

ISONIC 2009 PP Postprocessing Package for office PC provides the same functions as postprocessing SW on board ISONIC 2009 instrument

5.5.2.2. PUZZLE Postrocessing SW Package

PUZZLE postrpocessing allows composing of large 3D data files composed from several B-Scan scanning files. This provide compressing of large area data into one file and further off-line viewing and analysis

6. Conventional PE and TOFD Modalities

To operate conventional channel(s) of **ISONIC 2009 UPA Scope** in conventional PE and TOFD modalities refer to **ISONIC 2008 Operating Manual**. The latest version of this document is available for download at http://www.sonotronndt.com/pdf/om2008.pdf

Item	Order Code (Part #)	Note
ISONIC 2009 UPA-Scope – Portable Digital Phased Array Ultrasonic Flaw Detector and Recorder: 64 channels PA electronics and 1 independent channel for connection of conventional and TOFD probes	SA 804900	The following chapters of ISONIC 2008 Operating Manual are applicable: 5, 6, 8, 9, 10
ISONIC 2009 UPA-Scope – Portable Digital Phased Array Ultrasonic Flaw Detector and Recorder: 64 channels PA electronics and 8 independent channels for connection of conventional and TOFD probes	SA 804902	The following chapters of ISONIC 2008 Operating Manual are applicable: 5, 6, 7, 8, 9, 10

7. Incremental Encoders
Various encoders for may be used with **ISONIC 2009 UPA Scope**. For appropriate encoder data cable and connector pin-out contact

□ Nearest Sonotron NDT representative

OR

Directly to Sonotron NDT – e-mail to <u>support@sonotronndt.com</u> with subject ISONIC 2009 UPA Scope encoder connection

1

Improper cable out-coming from custom made encoder for proprietary inspection tasks may lead to warranty exempted damaging ISONIC 2009 UPA Scope instrument

To calibrate / add to database / encoder click on	
The proceed according to paragraph 8.4 of ISONIC 2008 Operating Manual . The latest version of this document is	1 International
available for download at http://www.sonotronndt.com/pdf/om2008.pdf	2 Encoders
	3 Printer Selection
	4 Back

8. Miscellaneous

8.1. International Settings

1 Opera 2 Settin 3 Postproce	essing	1 International 2 Encoders 3 Printer Selection 4 Back	ß					
In the PA Modality Start Menu slick on settings or press F2 then click on ress F1 :								
1 Language								
2 Measurement Unit								
	3 Back							

This will allow setting of dialogue language (English, Chinese, Portuguese, etc) and measuring units (metric or imperial)

8.2. Printer Selection

	1 Operate 2 Settings 3 Postprocessing 4 Back	1 8	2 1 3 Prin	ternational Encoders Iter Selection	14				
In the PA Modality Start Menu slick on section or press F2 then click on Printer Selection or press F3 :									
1 International Image: Select Philon Image: Select Philon									
Select printer among available in the list then click on									

8.3. Exit to Windows



In the ISONIC 2009 UPA-Scope Start Screen click on or press F3 to proceed with Windows XP Embedded settings of ISONIC 2009 UPA-Scope instrument. To return to ISONIC 2009 UPA-

Scope Start Screen double click on icon

1

Exit to Windows is required for:

- Connection to network
 - o Printing inspection results to network printer
 - Transferring data to / from remote PC
- □ Installing printer driver(s)
- Quasi-disk management

In order to prevent overloading of **ISONIC 2009 UPA Scope** quasi-disk and memory with data and non **ISONIC 2009 UPA Scope** SW that may affect instrument performance it's not allowed to install non **ISONIC 2009 UPA Scope** SW except drivers noted above. Affecting of instrument performance through installing on non **ISONIC 2009 UPA Scope** SW except drivers noted above is the warranty exemption damage

8.4. Connection to Network

To connect **ISONIC 2009 UPA Scope** to local area network use Ethernet connector (refer to paragraph 4.2 of this Operating Manual). Default factory settings are made for most typical connection to DHCP enabled network with obtaining IP automatically

8.5. External USB Devices

8.5.1. Mouse

Use one of 2 USB Connectors (refer to paragraph 4.2 of this Operating Manual). **ISONIC 2009 UPA Scope** founds and registers external USB mouse automatically through standard Windows routine. Microsoft optical mouse is recommended

8.5.2. Keyboard

Use one of 2 USB Connectors (refer to paragraph 4.2 of this Operating Manual). **ISONIC 2009 UPA Scope** founds and registers USB keyboard automatically through standard Windows routine. Microsoft keyboard is recommended

8.5.3. Memory Stick (Disk on Key)

Use one of 2 USB Connectors (refer to paragraph 4.2 of this Operating Manual). **ISONIC 2009 UPA Scope** running founds and registers USB memory stick (disk on key) automatically through standard Windows routine

8.5.4. Printer

Use one of 2 USB Connectors (refer to paragraph 4.2 of this Operating Manual). Preliminary driver setup is required. To install driver use network connection or USB memory stick (disk on key)

8.6. External VGA screen / VGA projector

Connect to appropriate connector (refer to paragraph 4.2 of this Operating Manual) while at least one of 2 devices either **ISONIC 2009 UPA Scope** or external screen / projector is switched OFF then switch on one or both devices

8.7. SW Upgrade

Refer to http://www.sonotronndt.com/support.htm in the Internet

8.8. Charging Battery

Battery of **ISONIC 2009 UPA Scope** may be charged while disconnected from the unit. The special charger is required (refer to Chapter 3 of this Operating Manual). Connect charger to the battery as it is shown below



There is **Charge** LED on the charger. While charging the battery this LED emits solid light. **Charge** LED starts flashing upon charge is completed

()

If a battery is new and almost completely discharged then "boiling" effect in the electrolyte may start earlier than battery is fully charged. In order to prevent battery charger stops on detecting boiling "boiling" effect:

- If temperature inside battery does not exceed 60°C deg limit then Charge LED starts flashing for such case it is necessary to disconnect charger from mains for few minutes and to connect it to mains again. The normal charging will continue
- If temperature inside battery exceeds 60°C deg limit then Temp LED starts flashing for such case it is necessary to disconnect charger from mains for at least 2 hours and to connect it to mains again. The normal charging will continue

After few charge / discharge cycles battery becomes "trained" and probability of "boiling" effect decreases to almost zero

8.9. Silicon Rubber Jacket

Use tweezers to remove the plastic screw caps from both sides of the handle:



Remove screw and washer from each side of the handle:



Put aside handle and all other parts:



Slip the Silicone Rubber Jacket around the machine:



Make sure the Silicone Rubber Jacket fits properly and covers all edges:



A view from the backside:



Slide the handle back in place (with the metal parts on each side):



Screw-in tightly at on each side of the handle:



Put back the plastic screw caps at each side by pushing them inwards until they lock and click:



DONE!!

